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1. General Description

HE84G770 is a member of 8-bit Micro-controller series developed by King Billion Electronics. External address and data buses are provided to access external memory. This chip has 6400 pixel, 16 gray-scale LCD driver built-in with 4 different configurations, and up to 36-bit general purpose I/O ports. The built-in OP comparator can be used with light, voice, temperature and humility sensor or used to detect the battery low. The 8-bit current-type D/A converter and PWM driver output provides the complete speech output solutions. The 1M bytes ROM and 6K bytes RAM can be used for the storage of large speech data, image and text, etc. An UART is included to provide the serial communication capability. IR output makes it suitable for remote control applications.

The instruction sets of HE80004H series is easy to learn and simple to use. There are only thirty-two instructions and four addressing modes. Most of instructions take only 3 oscillator clocks to complete. The performance and low power consumption make it suitable for battery-powered applications such as translator, data bank, educational toy, digital voice recorder, etc.

2. Features

✓ Operation Voltage: $2.4V \sim 3.6V$

✓ Dual Clock System: Fast clock: 32768 Hz ~ 8 MHz

Slow clock: 32768 Hz

✓ Four Operation Modes: Fast, Slow, Idle, Sleep modes.

✓ Internal ROM: 1M Bytes (512K Byte Program ROM, 512K Byte Data ROM)

✓ Internal RAM: 6K Bytes (Shared with LCD RAM).

- ✓ $6 \sim 36$ bit Bi-directional general purpose I/O port with push-pull or open-Drain output type selectable for each I/O pin by mask option.
- ✓ Up to 6400 pixels with 16, 4 gray-scale or Black/White LCD driver.
- ✓ Segment extender interface with KDGS80.
- ✓ 4 LCD configurations: $[32 \times 128]$, $[48 \times 112]$, $[64 \times 96]$, $[80 \times 80]$.
- ✓ Built-in LCD power supply with input power regulator, voltage multiplier circuit and bias generating circuit.
- ✓ PWM output.
- ✓ 8-bit current-type DAC output.
- ✓ Built-in OP comparator.
- ✓ Built-in UART for serial communication.
- ✓ IR output.
- ✓ Low voltage reset: 2.2V
- ✓ Low voltage detection: 2.4V, 2.6V, 2.8V and 3.0V
- ✓ Built-in keyboard auto scan hardware for up to 4×20 key matrix (shared with LCD SEG pins) not only reduces the hardware cost, but also reduces the firmware effort.
- ✓ Watchdog timer.
- ✓ Two 16-bit timers and one time-base timer.
- ✓ Two external interrupts, three internal timer interrupts and one internal UART interrupt.
- ✓ Instruction set: 32 instructions, 4 addressing modes.

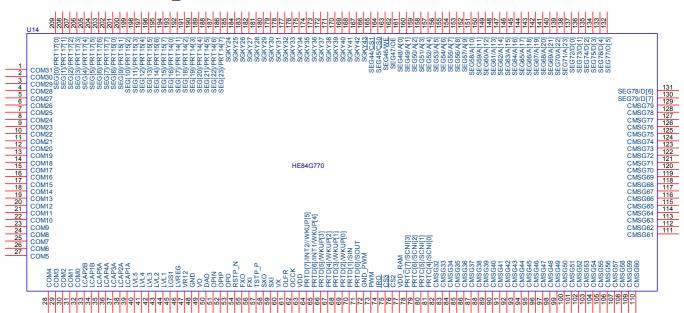




3. Functional Block Diagram

SEG COM	LCD Driver	8 Bit CPU	Fast Clock OSC.	FXI, FXO
LCAP?A, LCAP?B, VR12 LVL[51], LGS1, LVREG	LCD Power Supply	1 MB ROM	Slow Clock OSC	SXI, SXO
OLFR, OCCK	Segment Ext. Interface	6 KB RAM	PWM	PWM
SEGD, SEGA	Ext. Memory Interface	TC2	DAC	VO, DAO
PRTC, PRTD PRT14, PRT15, PRT17	I/O Port	TB WDT	OP Amp	OPO, OPIN, OPIP
SIN, SOUT	UART	LVR LVD	IR	IRO

4. Pin Description



Pin Name	I/O	Description
COM[310]	О	LCD COMMON Driver pads.
LCAP2B	О	Charge Pump Capacitor Pin.
LCAP1B	О	Charge Pump Capacitor Pin.
LCAP5A	О	Charge Pump Capacitor Pin.
LCAP4A	О	Charge Pump Capacitor Pin.
LCAP3A	О	Charge Pump Capacitor Pin.
LCAP2A	О	Charge Pump Capacitor Pin.





LCAPIA O Charge Pump Capacitor Pin.	Pin Name	I/O	Description
LVL4 P LCD Bias Voltage 4 LVL3 P LCD Bias Voltage 3 LVL1 P LCD Bias Voltage 2 LVL1 P LCD Bias Voltage 1 LGS1 I Regulator Voltage Setting LVREG O Voltage Regulator Output. VDD is regulated to generate LVREG, which is in turns pumped to LVL5. Adjust resistor between LGS1 and LVREG to set LVREG voltage. VR12 I Charge Pump Input. The buffered output of the fine-adjusted VREG. GND P Power Ground Input. VO O DAC Output. DAO O Alternate output of DAC. OPIN 1 Inverting input of OP Amp. OPO O Output of OP Amp. OPO O Usystem Reset Input Pin. Level trigger, active low on this pin will put the chip in reset state. External fast clock pin. Two types of oscillator can be selected by MO EXTAL (0° for RC External fast clock pin. Two types of oscillator, one crystal needs to be between FXI and GND. For crystal oscillator, one crystal needs to be placed between FXI and GND. For crystal oscillator, one crystal needs to be between FXI and GND. For crystal oscillator, one crystal needs to be placed between FXI and FXO. Please refer to application for details. TSTP_P 1 Test input pin. Please bond this pad and reserve a test point on PCB for debugging. But for improving ESD, please connect this point with zero Ohm resistor to GND. External slow clock pins. Slow clock is clock source for LCD display, TIMER1, Time-Base source and the point with zero Ohm resistor to GND. External slow clock pins. Slow clock is clock source for LCD display, TIMER1, Time-Base source and the point with zero Ohm resistor to GND. External slow clock pins. Slow clock is clock source for LCD display, TIMER1, Time-Base source and the proper source of the proper s	LCAP1A	О	•
IVI.2	LVL5	P	LCD Bias Voltage 5.
LVL12 P LCD Bias Voltage 2 LVT.1 P I CD Bias Voltage 1 LCSI I Regulator Voltage Setting Voltage Regulator Output. VDD is regulated to generate LVREG, which is in turns pumped to LVREG Voltage Regulator Output. VDD is regulated to generate LVREG, which is in turns pumped to LVREG Voltage Regulator Output. VDD is regulated to generate LVREG, which is in turns pumped to LVREG VO O DAC Output. DAO O DAC Output. DAO O Alternate output of DAC. OPIN I Inverting input of OP Amp. OPO O Output of OP Amp. OPO O Output of OP Amp. OPO O Output of OP Amp. System Reset Input Pin. Level trigger, active low on this pin will put the chip in reset state. External fast clock pin. Two types of oscillator can be selected by MO_FXTAL ('0' for RC type and '1' for crystal type). For RC type oscillator, one resistor needs to be connected be between FXI and GND. For crystal oscillator, one crystal needs to be chanced be between FXI and SND. For crystal oscillator, one crystal needs to be placed between FXI and FXO. Please refer to application for details. TESTP_P I Test input pin. Please bond this pad and reserve a test point on PCB for debugging. But for improving ESD, please connect this point with zero Ohm resistor to GND. External slow clock pins. Slow clock is clock source for LCD display, TIMFR1, Time-Base On an other internal blocks. Both crystal and RC oscillator are provided. The slow clock type can be selected by mask option MO_SXTAL. Choose '0' for RC type and '1' for crystal socillator. VX I Input pin for x32 PLL circuit. Connect to external resistor and capacitors as shown in application circuit. OLCD frame signal for interfacing with LCD segment extender KDGS80. PCCK O I CD data load pin for interfacing with LCD segment extender KDGS80. PSTD[0]/SOUT PORT of the output type of I/O pad can also be selected by mask option MO_DPP[7.0] ('1' for push-pull and '0' for open-drain). As the output structure of I/O pad does not contain tri-state buffer. When using the I/O as input, '1' must be outputed before reading	LVL4	P	LCD Bias Voltage 4
LVLI P LCD Bias Voltage 1. LCSI 1 Regulator Voltage Setting Voltage Regulator Output. VDD is regulated to generate LVREG, which is in turns pumped to LVLS. Adjust resistor between LGSI and LVREG to set LVREG voltage. VR12 1 Charge Pump Input. The buffered output of the fine-adjusted VREG GND P Power Ground Input. VO 0 DAC Output. DAO 0 Alternate output of DAC. OPIN 1 Inverting input of OP Amp. OPIP 1 Non-inverting input of OP Amp. OPIP 0 Output fOP Amp. OPIP 1 Non-inverting input of OP Amp. OPIP 1 Non-inverting input of OP Amp. OPIP 1 System Reset Input Pin. Level trigger, active low on this pin will put the chip in reset state. External fast clock pin. Two types of oscillator can be selected by MO_EXTAL (*0') for RC FXO, Otype and *1' for crystal type.) For RC type oscillator, one crystal needs to be placed between FXI and FXO. Please refer to application for details. TSTP_P 1 Inverting input of PMD in Pin. Level trigger, active low on this pin will put the chip in reset state. External fast clock pin. Two types of oscillator, one crystal needs to be placed between FXI and FXO. Please refer to application for details. TSTP_P 1 Inverting pin. Please bond this pad and reserve a test point on PCB for debugging. But for improving ESD, please connect this point with zero Ohm resistor to GND. External slow clock pins. Slow clock is clock source for LCD display, TIMFR1, Time-Base SXO, on and other internal blocks. Both crystal and RC oscillator are provided. The slow clock type as he selected by mask option MO_SXTAL. Choose '0' for RC type and '1' for crystal oscillator. UVX 1 Input pin for x32 PLL circuit. Connect to external resistor and capacitors as shown in application circuit. Input pin pin for x32 PLL circuit. Connect to external resistor and capacitors as shown in application circuit. Selit bi-directional I/O port D. The output type of I/O pad can also be selected by mask option MO_DPTP.3 (1) (1' for push-pull and '0' for open-drain). As the output structure of I/O pad does not contain tr	LVL3	P	LCD Bias Voltage 3
LGSI I Regulator Voltage Setting UNREG O Voltage Regulator Output. VDD is regulated to generate LVREG, which is in turns pumped to LVL5. Adjust resistor between LGSI and LVREG to set LVREG voltage. VR12 1 Charge Pump Input. The buffered output of the fine-adjusted VREG. GND P Power Ground Input. VO O DAC Output. DAO O Alternate output of DAC. OPIN 1 Inverting input of OP Amp. OPIP 1 Non-inverting input of OP Amp. OPO O O Output of OP Amp. STFT N 1 System Reset Input Pin. Level trigger, active low on this pin will put the chip in reset state. External fast clock pin. Two types of oscillator can be selected by MO_EXTAL ('0' for RC FXO, Otype and '1' for crystal type). For RC type oscillator, one resistor needs to be connected between EXI and GND. For crystal oscillator, one crystal needs to be placed between FXI and GND. For crystal oscillator, one crystal needs to be placed between EXI and EXO. Please refer to application for details. TESTP_P 1 Testing pin Pin Please bond this pad and reserve a test point on PCB for debugging. But for improving ESD, please connect this point with zero Ohm resistor to GND. External slow clock pins. Slow clock is clock source for LCD display, TIMFR1, Time-Base On and other internal blocks. Both crystal and RC oscillator are provided. The slow clock type oscillator. INDITION TO CONTROL TO THE CONTROL OF THE	LVL2	P	LCD Bias Voltage 2
LVREG O Voltage Regulator Output. VDD is regulated to generate LVREG, which is in turns pumped to IV15. Adjust resistor between LGS1 and IVREG to set LVREG voltage. VR12 I Charge Pump Input. The buffered output of the fine-adjusted VREG GND P P Power Ground Input. DAC Output. DAC Output. DAC Output. DAC Output. DAC Output. O OIL Inverting input of OP Amp. OPP OO O Output of OP Amp. OPP OO O Output of OP Amp. System Reset Input Pin. Level trigger, active low on this pin will put the chip in reset state. External fast clock pin. Two types of oscillator can be selected by MO_FXTAL ('0' for RC type and '1' for crystal type). For RC type oscillator, one resistor needs to be connected between FXI and GND. For crystal oscillator, one crystal needs to be placed between FXI and FXO. Please refer to application for details. TSTP_P I Test input pin. Please bond this pad and reserve a test point on PCB for debugging. But for improving ESD, please connect this point with zero Ohn resistor to GND. External slow clock pins. Slow clock is clock source for LCD display, TIMERI, Time-Base and other internal blocks. Both crystal and RC oscillator are provided. The slow clock type can be selected by mask option MO_SXTAL. Choose '0' for RC type and '1' for crystal oscillator. VX I Imput pin for x32 PLL circuit. Connect to external resistor and capacitors as shown in application circuit. OLFR O LCD data load pin for interfacing with LCD segment extender KDGS80. OCCK O LCD data load pin for interfacing with LCD segment extender KDGS80. DCC data load pin for interfacing with LCD segment extender KDGS80. DCC data load pin for interfacing with LCD segment extender KDGS80. P Postive power Input. A 0.1 µf elecoupling capacitors should be placed as close to IC VDD and GND pads as possible for best decoupling effect. Bett bi-directional I/O port D. The output type of I/O pad can also be selected by mask option MO_DPP[7.0] ('1' for push-pull and '0' for open-drain). As the output structure of I/O pad does not contain tri-	LVL1	P	LCD Bias Voltage 1.
VR12	LGS1	I	Regulator Voltage Setting
VR12	LVREG	О	Voltage Regulator Output. VDD is regulated to generate LVREG, which is in turns pumped to LVL5. Adjust resistor between LGS1 and LVREG to set LVREG voltage.
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TSTP_P I Test input pin. Please bond this pad and reserve a test point on PCB for debugging. But for improving ESD, please connect this point with zero Ohm resistor to GND. External slow clock pins. Slow clock is clock source for LCD display, TIMER1, Time-Base and other internal blocks. Both crystal and RC oscillator are provided. The slow clock type can be selected by mask option MO_SXTAL. Choose '0' for RC type and '1' for crystal oscillator. VX I Input pin for x32 PLL circuit. Connect to external resistor and capacitors as shown in application circuit. OLFR O LCD frame signal for interfacing with LCD segment extender KDGS80. OCCK O LCD data load pin for interfacing with LCD segment extender KDGS80. Positive power Input. A 0.1 µF decoupling capacitors should be placed as close to IC VDD and GND pads as possible for best decoupling effect. 8-bit bi-directional I/O port D. The output type of I/O pad can also be selected by mask option MO_DPP[70] ('1' for push-pull and '0' for open-drain). As the output structure of I/O pad does not contain tri-state buffer. When using the I/O as input, '1' must be outputted before reading the pin. PRTD[1] shares pad with UART Receiver SIN pin. PRTD[1] shares pad with UART receiver SIN pin. PRTD[0] shares pad with UART transmitter SOUT pin. O Dedicated Ground for PWM output. The PWM output can drive speaker or buzzer directly. Set the bit2 of VOC register as one to turn on PWM. Using VDD & PWM to drive output device. The Infrared output. 4-bit bi-directional I/O port C. The output type of I/O pad can also be selected by mask option MO_CPP[74] ('1' for push-pull and '0' for open-drain). As the output structure of I/O pad does not contain tri-state buffer. When using the I/O as input, '1' must be outputted before reading the pin. PRTC[74] SCNI[30] PRTC[74] by shared with Key Scan Dedicated Input SCNI[30]. The Key Scan function can be disabled by clearing MO_LCDKEY mask option to '0'.	FXO, FXI	О,	External fast clock pin. Two types of oscillator can be selected by MO_FXTAL ('0' for RC
improving ESD, please connect this point with zero Ohm resistor to GND. External slow clock pins. Slow clock is clock source for LCD display, TIMER1, Time-Base O, and other internal blocks. Both crystal and RC oscillator are provided. The slow clock type can be selected by mask option MO_SXTAL. Choose '0' for RC type and '1' for crystal oscillator. Input pin for x32 PLL circuit. Connect to external resistor and capacitors as shown in application circuit. OLFR O LCD firame signal for interfacing with LCD segment extender KDGS80. VDD P Positive power Input. A 0.1 µF decoupling capacitors should be placed as close to IC VDD and GND pads as possible for best decoupling effect. 8-bit bi-directional I/O port D. The output type of I/O pad can also be selected by mask option MO_DPP[70] ('1' for push-pull and '0' for open-drain). As the output structure of I/O pad does not contain tri-state buffer. When using the I/O as input, '1' must be outputted before reading the pin. PRTD[72] can be used as wake-up pins. PRTD[76] can be as external interrupt sources. PRTD[1] shares pad with UART Receiver SIN pin. PRTD[0] shares pad with UART runsmitter SOUT pin. Dedicated Ground for PWM output. The PWM output can drive speaker or buzzer directly. Set the bit2 of VOC register as one to turn on PWM. Using VDD & PWM to drive output device. The Infrared output. 4-bit bi-directional I/O port C. The output type of I/O pad can also be selected by mask option MO_CPP[74] ('1' for push-pull and '0' for open-drain). As the output structure of I/O pad does not contain tri-state buffer. When using the I/O as input, '1' must be outputted before reading the pin. PRTC[74]/ SCNI[30] Branch Table T			
External slow clock pins. Slow clock is clock source for LCD display, TIMER1, Time-Base O, and other internal blocks. Both crystal and RC oscillator are provided. The slow clock type I can be selected by mask option MO_SXTAL. Choose '0' for RC type and '1' for crystal oscillator. VX I Input pin for x32 PLL circuit. Connect to external resistor and capacitors as shown in application circuit. OLFR O LCD frame signal for interfacing with LCD segment extender KDGS80. OCCK O LCD data load pin for interfacing with LCD segment extender KDGS80. Positive power Input. A 0.1 µF decoupling capacitors should be placed as close to IC VDD and GND pads as possible for best decoupling effect. 8-bit bi-directional I/O port D. The output type of I/O pad can also be selected by mask option MO_DPP[70] ('1' for push-pull and '0' for open-drain). As the output structure of I/O pad does not contain tri-state buffer. When using the I/O as input, '1' must be outputted before reading the pin. PRTD[1] shares pad with UART Receiver SIN pin. PRTD[0] shares pad with UART transmitter SOUT pin. O Dedicated Ground for PWM output. The PWM output can drive speaker or buzzer directly. Set the bit2 of VOC register as one to turn on PWM. Using VDD & PWM to drive output device. The Infrared output. 4-bit bi-directional I/O port C. The output type of I/O pad can also be selected by mask option MO_CPP[74] ('1' for push-pull and '0' for open-drain). As the output structure of I/O pad does not contain tri-state buffer. When using the I/O as input, '1' must be outputted before reading the pin. PRTC[74]/ SCNI[30] B the first provided the provided to the pro	TSTP_P	1 1 2 2 2	
VX I Input pin for x32 PLL circuit. Connect to external resistor and capacitors as shown in application circuit. OLFR O LCD frame signal for interfacing with LCD segment extender KDGS80. OCCK O LCD data load pin for interfacing with LCD segment extender KDGS80. VDD Positive power Input. A 0.1 μF decoupling capacitors should be placed as close to IC VDD and GND pads as possible for best decoupling effect. 8-bit bi-directional I/O port D. The output type of I/O pad can also be selected by mask option MO_DPP[70] ('1' for push-pull and '0' for open-drain). As the output structure of I/O pad does not contain tri-state buffer. When using the I/O as input, '1' must be outputted before reading the pin. PRTD[72] can be used as wake-up pins. PRTD[76] can be as external interrupt sources. PRTD[1] shares pad with UART Receiver SIN pin. PRTD[0] shares pad with UART transmitter SOUT pin. GND_PWM O Dedicated Ground for PWM output. The PWM output can drive speaker or buzzer directly. Set the bit2 of VOC register as one to turn on PWM. Using VDD & PWM to drive output device. The PWM output can drive speaker or buzzer directly. Set the bit2 of VOC register as one to turn on PWM. Using VDD & PWM to drive output device. BRO O The Infrared output. 4-bit bi-directional I/O port C. The output type of I/O pad can also be selected by mask option MO_CPP[74] ('1' for push-pull and '0' for open-drain). As the output structure of I/O pad does not contain tri-state buffer. When using the I/O as input, '1' must be outputted before reading the pin. PRTC[74]/ SCNI[30] PRTC[74] is shared with Key Scan Dedicated Input SCNI[30]. The Key Scan function can be disabled by clearing MO_LCDKEY mask option to '0'.	SXO, SXI		External slow clock pins. Slow clock is clock source for LCD display, TIMER1, Time-Base and other internal blocks. Both crystal and RC oscillator are provided. The slow clock type can be selected by mask option MO_SXTAL. Choose '0' for RC type and '1' for crystal
OCCK VDD P Cocce and GND pads as possible for best decoupling capacitors should be placed as close to IC VDD and GND pads as possible for best decoupling effect. 8-bit bi-directional I/O port D. The output type of I/O pad can also be selected by mask option MO_DPP[70] ('1' for push-pull and '0' for open-drain). As the output structure of I/O pad does not contain tri-state buffer. When using the I/O as input, '1' must be outputted before reading the pin. PRTD[0]/SOUT PRTD[1]/SIN PRTD[1]/Sin as the output structure of I/O pad does not contain tri-state buffer. When using the I/O as input, '1' must be outputted before reading the pin. PRTD[0]/Shares pad with UART Receiver SIN pin. PRTD[0]/Shares pad with UART transmitter SOUT pin. O Dedicated Ground for PWM output. The PWM output can drive speaker or buzzer directly. Set the bit2 of VOC register as one to turn on PWM. Using VDD & PWM to drive output device. The Infrared output. 4-bit bi-directional I/O port C. The output type of I/O pad can also be selected by mask option MO_CPP[74] ('1' for push-pull and '0' for open-drain). As the output structure of I/O pad does not contain tri-state buffer. When using the I/O as input, '1' must be outputted before reading the pin. PRTC[74]/SCNI[30] PRTC[74] is shared with Key Scan Dedicated Input SCNI[30]. The Key Scan function can be disabled by clearing MO_LCDKEY mask option to '0'.		I	Input pin for x32 PLL circuit. Connect to external resistor and capacitors as shown in
Positive power Input. A 0.1 μF decoupling capacitors should be placed as close to IC VDD and GND pads as possible for best decoupling effect. 8-bit bi-directional I/O port D. The output type of I/O pad can also be selected by mask option MO_DPP[70] ('1' for push-pull and '0' for open-drain). As the output structure of I/O pad does not contain tri-state buffer. When using the I/O as input, '1' must be outputted before reading the pin. PRTD[0]/SOUT PRTD[1] shares pad with UART Receiver SIN pin. PRTD[1] shares pad with UART transmitter SOUT pin. O Dedicated Ground for PWM output. PWM O The PWM output can drive speaker or buzzer directly. Set the bit2 of VOC register as one to turn on PWM. Using VDD & PWM to drive output device. IRO O The Infrared output. 4-bit bi-directional I/O port C. The output type of I/O pad can also be selected by mask option MO_CPP[74] ('1' for push-pull and '0' for open-drain). As the output structure of I/O pad does not contain tri-state buffer. When using the I/O as input, '1' must be outputted before reading the pin. PRTC[74] B PRTC[74] is shared with Key Scan Dedicated Input SCNI[30]. The Key Scan function can be disabled by clearing MO_LCDKEY mask option to '0'.	OLFR	О	LCD frame signal for interfacing with LCD segment extender KDGS80.
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option MO_DPP[70] ('1' for push-pull and '0' for open-drain). As the output structure of I/O pad does not contain tri-state buffer. When using the I/O as input, '1' must be outputted before reading the pin. PRTD[0]/SOUT PRTD[0]/SOUT PRTD[1] shares pad with UART Receiver SIN pin. PRTD[0] shares pad with UART transmitter SOUT pin. GND_PWM O Dedicated Ground for PWM output. PWM O The PWM output can drive speaker or buzzer directly. Set the bit2 of VOC register as one to turn on PWM. Using VDD & PWM to drive output device. IRO O The Infrared output. 4-bit bi-directional I/O port C. The output type of I/O pad can also be selected by mask option MO_CPP[74] ('1' for push-pull and '0' for open-drain). As the output structure of I/O pad does not contain tri-state buffer. When using the I/O as input, '1' must be outputted before reading the pin. PRTC[74]/ SCNI[30] PRTC[74] is shared with Key Scan Dedicated Input SCNI[30]. The Key Scan function can be disabled by clearing MO_LCDKEY mask option to '0'. VDD_RAM P Dedicated power input for RAM	VDD	P	Positive power Input. A $0.1~\mu F$ decoupling capacitors should be placed as close to IC VDD and GND pads as possible for best decoupling effect.
PWM O The PWM output can drive speaker or buzzer directly. Set the bit2 of VOC register as one to turn on PWM. Using VDD & PWM to drive output device. IRO O The Infrared output. 4-bit bi-directional I/O port C. The output type of I/O pad can also be selected by mask option MO_CPP[74] ('1' for push-pull and '0' for open-drain). As the output structure of I/O pad does not contain tri-state buffer. When using the I/O as input, '1' must be outputted before reading the pin. PRTC[74] is shared with Key Scan Dedicated Input SCNI[30]. The Key Scan function can be disabled by clearing MO_LCDKEY mask option to '0'. VDD_RAM P Dedicated power input for RAM	PRTD[72] PRTD[1]/SIN PRTD[0]/SOUT		As the output structure of I/O pad does not contain tri-state buffer. When using the I/O as input, '1' must be outputted before reading the pin. PRTD[72] can be used as wake-up pins. PRTD[76] can be as external interrupt sources. PRTD[1] shares pad with UART Receiver SIN pin.
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PRTC[74]/ SCNI[30] 4-bit bi-directional I/O port C. The output type of I/O pad can also be selected by mask option MO_CPP[74] ('1' for push-pull and '0' for open-drain). As the output structure of I/O pad does not contain tri-state buffer. When using the I/O as input, '1' must be outputted before reading the pin. PRTC[74] is shared with Key Scan Dedicated Input SCNI[30]. The Key Scan function can be disabled by clearing MO_LCDKEY mask option to '0'. VDD_RAM P Dedicated power input for RAM	PWM		The PWM output can drive speaker or buzzer directly. Set the bit2 of VOC register as one to
option MO_CPP[74] ('1' for push-pull and '0' for open-drain). As the output structure of I/O pad does not contain tri-state buffer. When using the I/O as input, '1' must be outputted before reading the pin. PRTC[74] is shared with Key Scan Dedicated Input SCNI[30]. The Key Scan function can be disabled by clearing MO_LCDKEY mask option to '0'. VDD_RAM P Dedicated power input for RAM	IRO	О	The Infrared output.
VDD_RAM P Dedicated power input for RAM	PRTC[74]/ SCNI[30]		4-bit bi-directional I/O port C. The output type of I/O pad can also be selected by mask option MO_CPP[74] ('1' for push-pull and '0' for open-drain). As the output structure of I/O pad does not contain tri-state buffer. When using the I/O as input, '1' must be outputted before reading the pin. PRTC[74] is shared with Key Scan Dedicated Input SCNI[30]. The Key Scan function
_	VDD RAM	P	





Pin Name	I/O	Description
		COM drivers or SEG drivers can be selected by mask option MO_COM[10]. Please refer to LCD driver configuration for details.
SEG[7972]/ D[70]	О	LCD segment SEG[7972] outputs share pads with data bus D[70] of external memory.
SEG[7148]/ A[230]	О	LCD segment SEG[7148] outputs share pads with address bus A[230] of external memory.
OE/SEG[47]	О	Output Enable control of external memory shares pad with SEG[47]. The function of the pin is selected by mask option MO_EXMEM. When used as Output Enable control pin, this pin control the tri-state buffer of external memory data bus.
WE/SEG[46]	О	Write Enable 0 of external memory shares pad with SEG[46]. The function of the pin is selected by mask option MO_EXMEM. When used as Write Enable control pin, this pin controls Write Enable input of the external memory device.
CS0/SEG[45]	О	Chip Enable 0 of external memory shares pad with SEG[45]. The function of the pin is selected by mask option MO_EXMEM. When used as Chip Enable control pin, this pin select or de-select the external memory device based on the address been accessed.
CS1/SEG[44]	О	Chip Enable 1 of external memory shares pad with SEG[44]. The function of the pin is selected by mask option MO_EXMEM. When used as Chip Enable control pin, this pin select or de-select the external memory device based on the address been accessed.
CS2	О	Chip Enable 2 of external memory. This pin select or de-select the external memory device based on the address been accessed.
CS3	О	Chip Enable 3 of external memory. This pin select or de-select the external memory device based on the address been accessed.
SGKY[4324]	О	LCD segments share pads with key scan out SCNO[190]. The key scan function of these pins can be disabled by mask option clearing MO_LCDKEY to '0', then SGKY[4324] function as LCD segment driver only. Setting MO_LCDKEY to '1' will turn on the key scan function.
PRT14[70]/ SEG[2316]	B/ O	8 bits bi-directional I/O port 14 are shared with LCD segment pads SEG[2316]. The function of the pad can be selected individually by mask options MO_LIO14[70]. ('1' for LCD and '0' for I/O). The output type of I/O pad can also be selected by mask option MO_14PP[70] (1 for push-pull and '0' for open-drain). As the output structure of I/O pad does not contain tri-state buffer. When using the I/O as input, "1" must be outputted before reading.
PRT15[70]/ SEG[158]	B/ O	8 bits bi-directional I/O port 15 are shared with LCD segment pads SEG[158]. The function of the pad can be selected individually by mask options MO_LIO15[70]. ('1' for LCD and '0' for I/O). The output type of I/O pad can also be selected by mask option MO_15PP[70] (1 for push-pull and '0' for open-drain). As the output structure of I/O pad does not contain tri-state buffer. When using the I/O as input, "1" must be outputted before reading.
PRT17[70]/ SEG[70]	B/ O	8 bits bi-directional I/O port 17 are shared with LCD segment pads SEG[70]. The function of the pad can be selected individually by mask options MO_LIO17[70]. ('1' for LCD and '0' for I/O). The output type of I/O pad can also be selected by mask option MO_17PP[70] (1 for push-pull and '0' for open-drain). As the output structure of I/O pad does not contain tri-state buffer. When using the I/O as input, "1" must be outputted before reading.





5. ROM Map Configurations

The chip has built-in 1M bytes internal ROM including 512K bytes program ROM and 512K bytes data ROM. In addition, address and data buses are provided to access External ROM. The MCU can access up to 4 MB Program ROM and up to 16 MB Data space through external buses. The SEG[79..72], SEG[71..44] pads are used as either data and address buses for external ROM or LCD segment driver pads depending on the mask option MO_EXMEM. When the external ROM mask option is selected, the MCU will retrieve the instructions and data from external ROM through the address and data buses and the SEG[79..44] will not be LCD segment signals.

The bit $14 \sim 15$ bit of 16-bit logical program address can be mapped to any one of 256 pages through mapping registers PSA1, PSA2, PSA3. As logical page 0 can not be moved and is always physical page 0, the PSA1 \sim PSA3 contain the physical page addresses of logical pages $1 \sim 3$.

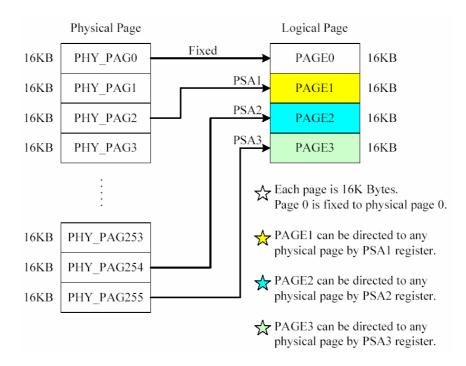
	Logical Address														
A15	A14	A13	A12	A11	A10	A9	A8	A7	A6	A5	A4	A3	A2	A1	A0
Page	Addr.	A13	A12	A11	A10	A9	A8	A7	A6	A5	A4	A3	A2	A1	A0

A[1514]	Logical Page	Physical Page Address	Physical Address
00	0	0	00 A[130]
01	1	PSA1	PSA1+A[130]
10	2	PSA2	PSA2+A[130]
11	3	PSA3	PSA3+A[130]

Register	Address	Type		Bits Definition							
PSA1	0x2C	R/W	A21	A20	A19	A18	A17	A16	A15	A14	0x01
PSA2	0x2D	R/W	A21	A20	A19	A18	A17	A16	A15	A14	0x02
PSA3	0x2E	R/W	A21	A20	A19	A18	A17	A16	A15	A14	0x03





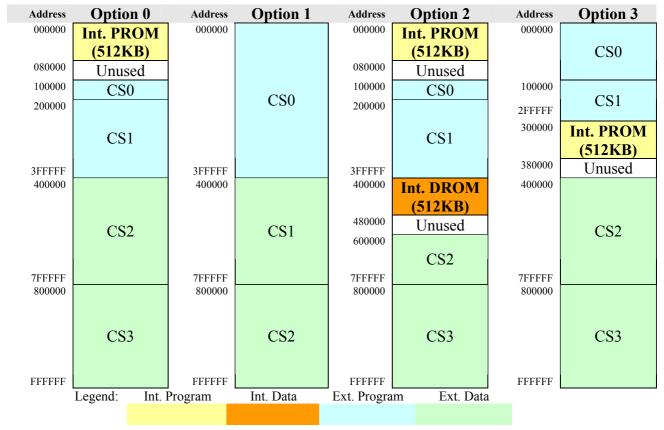


There are four configurations for external memory as determined by mask option MO_PMODE. For example, when option 0 is selected, 512 KB of internal ROM will occupy the address range from $0x000000 \sim 0x07FFFF$ of memory space, while CS1 controls external memory device whose address ranges from 0x200000 to 3FFFFF, etc. If the Option 1 is selected, the internal program/data ROM will be skipped and the external ROM will be active by CS0 \sim 2.

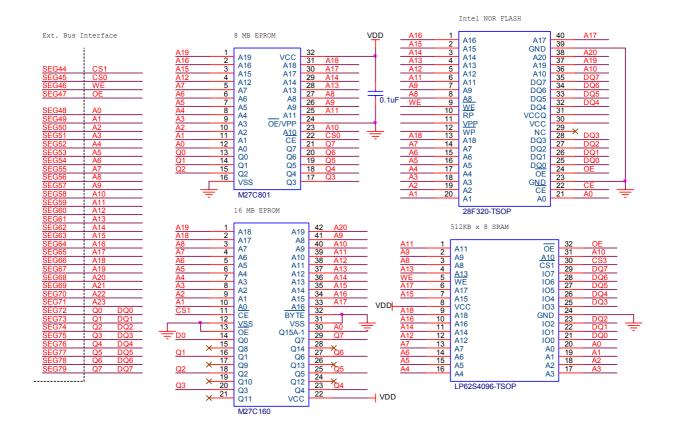
MO_ PMODE [10]	Configuration
00	Option 0
01	Option 1
10	Option 2
11	Option 3







Note: Option2 shall be selected when the internal "Data ROM" is used.







6. External RAM/Flash Memory

The external memory devices can be mask ROM, static RAM, or NOR type FLASH memory. Most NOR type FLASH memory and RAM can be used as external storage for both program and data, so program can be downloaded to external memory devices for future execution. However, there are some limitations. When the data is to be written to external devices, the loader must reside in internal program space. In other words, the loader program must be in internal ROM. When download is completed, the program in the external memory can be run.

The data written to external memory devices is through a command interface composed of AC, EXMC and EXMD registers for setting up the memory addresses, switching memory buses, generating read/write pulse, read/write memory contents, etc. When writing finishes, external memory can be switched back the external address and data bus for CPU to fetch data and instructions.

Writing to address registers is through a common register AC. Writing to AC will write data to ACL, ACH, and then ACP in cyclic order. The sequence will be reset by an access to EXMD register. Therefore, it is advisable to make a dummy read to EXMD register before writing to AC, so that the first write will be made to ACL.

AC	Mode	Description	Reset Value
ACL	R/W	Address Counter Low for AC7 ~ AC0	""
ACH	R/W	Address Counter High for AC15 ~ AC8	""
ACP	R/W	Address Counter Page for AC23 ~ AC16	"

ACL: Lowest Significant Byte of Address Counter.

ACH: 2nd Byte of Address Counter.

ACP: Most Significant Byte of Address Counter.

Register	Mode		Description								
EXMC	W	-	-	-	-	-	DNLD	RD	WR	"011"	

DNLD: Switch the bus to download bus.

RD: Read pulse control. WR: Write pulse control.

After address setup, the data can be written to address device through EXMD register. Program must generate the required write pulse by firmware. The address counter AC will automatically increment with each read/write access.

Register	Type		Description							
EXMD	R/W	D7	D6	D5	D4	D3	D2	D1	D0	""

The procedure for downloading data from I/O or any other sources, i.e. command mode ROM device is as follows:

1. Switch the external memory to download bus by setting the DNLD bit of EXMC register.





- 2. Make a dummy read to EXMD register to reset the AC pointer.
- 3. Set up the address for transferring data by first writing to ACL, and then ACH and ACP with the first 3 writes to register.
- 4. Start writing to addressed device by first writing 1 byte of data to EXMD register, clear WR bit of CMD register and set it again, the AC will increment with each write pulse.
- 5. To read addressed device, clear RD bit of EXMC register, read EXMD register and set RD bit again. The AC will also increment with each read pulse. Read back for verification is optional. Please note that read back can also be made through external address and data bus when the bus is switched back to program bus.
- 6. Switch back to normal bus for program execution and data access by clearing the DNLD bit of EXMC register.

Please note that NOR FLASH memory from different manufacturers such as Intel, AMD, SST, etc. requires various command sequence to set up. Programmer still needs to follow the respective specifications of the vendors.

7. LCD Display RAM Map

The gray-scale LCD driver can be configured to be a 16 gray-scale, 4 gray-scales or black and white display by mask option MO_GRAY_MODE.

MO_GRAY_MODE[10]	Gray levels
00	16
01	4
10	2 (B/W)
11	2 (B/W)

For 4 gray-scale displays, 2-bit of RAM is required for each pixel and 4 bit for 16 gray-scale display, 1-bit for black and white display. For different LCD configuration, the LCD display RAM is arranged differently. The following figure shows one byte of RAM in different LCD configurations:

0F	0E	0D	0C	0B	0A	09	08	07	06	05	04	03	02	01	00	l
XX																

	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
Black/White	SEG7 SEG6		SEG5 SEG4		SEG3	SEG2	SEG1	SEG0
4 Gray scales	SE	G3	SEG2		SE	G1	SEG0	
16 Gray scales		SE	G1		SEG0			

The 16 Gray Scale register GRAY0 \sim GRAYF is the mapping register between the levels selected in RAM and the real gray scale. In other words, if the content of GRAY0 is 0x03, when value of a certain pixel is 0, the displayed effect will correspond to actual gray level 3. The 16 gray scale display use all 16 registers GRAY0 \sim GRAYF to select among 32 available gray levels to correspond to level 0 \sim 15, while





4 gray scale display utilizes registers GRAY0 \sim GRAY3 to select among 32 gray levels to correspond to level 0 \sim 3. Thus user can pick the gray levels which give the best and most linear effect.

16 Gray-scale registers share a common register address GRAY16. When writing is made to the register, it will step down to next register in order. The writing sequence can be reset by clearing bit 5 of LCDC register.

GRAY16			Field						
Seq.	Bit4	Bit3	Bit2	Bit1	Bit0	Reset			
1			GRAY0			0x00			
2			GRAY1			0x02			
3			GRAY2			0x04			
4			GRAY3			0x06			
5			GRAY4			0x08			
6			GRAY5			0x0A			
7		GRAY6							
8			GRAY7			0x0E			
9			GRAY8			0x10			
10			GRAY9			0x12			
11			GRAYA			0x14			
12			GRAYB			0x16			
13			GRAYC			0x18			
14		GRAYD							
15	GRAYE								
16			GRAYF			0x1E			

8. LCD driver configurations

There are 4 LCD configurations selectable by mask option MO_COM[1:0] for this chip. The function of CMSG[79..32] in each configuration is listed in the following table.

MO_COM[1:0]	Configuration COM x SEG	CMSG[7964] Function	CMSG[6348] Function	CMSG[4732] Function
00	32 x 128	SEG[8095]	SEG[96111]	SEG[112127]
01	48 x 112	SEG[8095]	SEG[96111]	COM[4732]
10	64 x 96	SEG[8095]	COM[6348]	COM[4732]
11	80 x 80	COM[7964]	COM[6348]	COM[4732]





OMXSEG	32X128	48X112	64X96	80X80
CMSG32	SEG127	COM32	COM32	COM32
CMSG33	SEG126	COM33	COM33	COM33
CMSG34	SEG125	COM34	COM34	COM34
CMSG35	SEG124	COM35	COM35	COM35
CMSG36	SEG123	COM36	COM36	COM36
CMSG37	SEG122	COM37	COM37	COM37
CMSG38	SEG121	COM38	COM38	COM38
CMSG39	SEG120	COM39	COM39	COM39
CMSG40	SEG119	COM40	COM40	COM40
CMSG41	SEG118	COM41	COM41	COM41
CMSG42	SEG117	COM42	COM42	COM42
CMSG43	SEG116	COM43	COM43	COM43
CMSG44	SEG115	COM44	COM44	COM44
CMSG45	SEG114	COM45	COM45	COM45
CMSG46	SEG113	COM46	COM46	COM46
CMSG47	SEG112	COM47	COM47	COM47
CMSG48	SEG111	SEG111	COM48	COM48
CMSG49	SEG110	SEG110	COM49	COM49
CMSG50	SEG109	SEG109	COM50	COM50
CMSG50	SEG109	SEG109	COM51	COM51
CMSG52	SEG107	SEG107	COM52	0002
CMSG53	SEG106	SEG106	COM53	COM53
CMSG54	SEG105	SEG105	COM54	COM54 COM55
CMSG55	SEG104	SEG104	COM55	
CMSG56	SEG103	SEG103	COM56	COM56
CMSG57	SEG102	SEG102	COM57	COM57
CMSG58	SEG101	SEG101	COM58	COM58
CMSG59	SEG100	SEG100	COM59	COM59
CMSG60	SEG99	SEG99	COM60	COM60
CMSG61	SEG98	SEG98	COM61	COM61
CMSG62	SEG97	SEG97	COM62	COM62
CMSG63	SEG96	SEG96	COM63	COM63
CMSG64	SEG95	SEG95	SEG95	COM64
CMSG65	SEG94	SEG94	SEG94	COM65
CMSG66	SEG93	SEG93	SEG93	COM66
CMSG67	SEG92	SEG92	SEG92	COM67
CMSG68	SEG91	SEG91	SEG91	COM68
CMSG69	SEG90	SEG90	SEG90	COM69
CMSG70	SEG89	SEG89	SEG89	COM70
CMSG71	SEG88	SEG88	SEG88	COM71
CMSG72	SEG87	SEG87	SEG87	COM72
CMSG73	SEG86	SEG86	SEG86	COM73
CMSG74	SEG85	SEG85	SEG85	COM74
CMSG75	SEG84	SEG84	SEG84	COM75
CMSG76	SEG83	SEG83	SEG83	COM76
CMSG77	SEG82	SEG82	SEG82	COM77
CMSG78	SEG81	SEG81	SEG81	COM78
CMSG79	SEG80	SEG80	SEG80	COM79

Since there are four LCD driver configurations available for selection by mask option, the RAM map of LCD drivers is listed below for all configurations. Any unused RAM as marked with '*' sign can be used as general purposed RAM by application programs.

8.1. 16 Gray Scale LCD Display RAM Map

		32x128	48x112	64x96	80x80		
Page		F 0	F 0	F 0	F 0		
1	00	S31 ~ S00	S31 ~ S00	S31 ~ S00	S31 ~ S00		
	10	S63 ~ S32	S63 ~ S32	S63 ~ S32	S63 ~ S32	COM0	
	20	S95 ~ S64	S95 ~ S64	S95 ~ S64	* S80 ~ S64	COMO	
	30	S127 ~ S96	* S112 ~ S96	*	*		
	40	S31 ~ S00	S31 ~ S00	S31 ~ S00	S31 ~ S00		
	50	S63 ~ S32	S63 ~ S32	S63 ~ S32	S63 ~ S32	COM1	
	60	S95 ~ S64	S95 ~ S64	S95 ~ S64	* S80 ~ S64	COMI	
	70	S127 ~ S96	* S112 ~ S96	*	*		
	80	S31 ~ S00	S31 ~ S00	S31 ~ S00	S31 ~ S00		
	90	S63 ~ S32	S63 ~ S32	S63 ~ S32	S63 ~ S32	COM2	
	A0	S95 ~ S64	S95 ~ S64	S95 ~ S64	* S80 ~ S64	COMZ	
	В0	S127 ~ S96	* S112 ~ S96	*	*		
	C0	S31 ~ S00	S31 ~ S00	S31 ~ S00	S31 ~ S00	COM3	





2 70 S127 ~ S96 * S112 ~ S96 * * 80 S31 ~ S00 S31 ~ S00 S31 ~ S00	\$80 ~ \$64 \$\cdot \text{S00}\$
$\begin{array}{ c c c c c c c }\hline E0 & S95 \sim S64 & S95 \sim S64 & * & * & * \\\hline F0 & S127 \sim S96 & * & S112 \sim S96 & * & * \\\hline 00 & S31 \sim S00 & S31 \sim S00 & S31 \sim S00 & S31 \sim \\\hline 10 & S63 \sim S32 & S63 \sim S32 & S63 \sim S32 & S63 \sim \\\hline 20 & S95 \sim S64 & S95 \sim S64 & S95 \sim S64 & * \\\hline 30 & S127 \sim S96 & * & S112 \sim S96 & * & * \\\hline 40 & S31 \sim S00 & S31 \sim S00 & S31 \sim S00 & S31 \sim \\\hline 50 & S63 \sim S32 & S63 \sim S32 & S63 \sim S32 & S63 \sim \\\hline 60 & S95 \sim S64 & S95 \sim S64 & S95 \sim S64 & * \\\hline 2 & 70 & S127 \sim S96 & * & S112 \sim S96 & * & * \\\hline 80 & S31 \sim S00 & S31 \sim S$	\$80 ~ \$64 \$\displays{c}\$\$\displays{c}\$\$\displays{c}\$\$\$S32\$\$\$COM4
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	- S00 - S32 COM4
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	- S32 COM4
$\begin{array}{ c c c c c c }\hline 10 & S63 \sim S32 & S63 \sim S32 & S63 \sim S32 & S63 \sim \\ \hline 20 & S95 \sim S64 & S95 \sim S64 & S95 \sim S64 & * \\ \hline 30 & S127 \sim S96 & * & S112 \sim S96 & * & * \\ \hline 40 & S31 \sim S00 & S31 \sim S00 & S31 \sim S00 & S31 \sim \\ \hline 50 & S63 \sim S32 & S63 \sim S32 & S63 \sim S32 & S63 \sim \\ \hline 60 & S95 \sim S64 & S95 \sim S64 & S95 \sim S64 & * \\ \hline 70 & S127 \sim S96 & * & S112 \sim S96 & * & * \\ \hline 80 & S31 \sim S00 & S31 $	- S32 COM4
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	COM4
30 \$127 \circ \$96\$ * \$\$112 \circ \$96\$ * * 40 \$31 \circ \$800\$ 50 \$63 \circ \$832\$ 60 \$95 \circ \$864\$ \$95 \circ \$864\$ \$95 \circ \$864\$ * 70 \$127 \circ \$96\$ * \$112 \circ \$96\$ * 80 \$31 \circ \$800\$ \$31 \circ \$800\$ \$31 \circ \$800\$ \$31 \circ \$800\$	S80 ~ S64
40 \$31 \circ \$500 <	:
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	
2	- S00
2 70 S127 ~ S96 * S112 ~ S96 * * 80 S31 ~ S00 S31 ~ S00 S31 ~ S00	(COM5
2 80 S31 ~ S00 S31 ~ S00 S31 ~ S00 S31 ~ S00	S80 ~ S64
80 S31 ~ S00 S31 ~ S00 S31 ~ S00 S31 ~	1
	- S00
90 S63 ~ S32 S63 ~ S32 S63 ~ S32	COM6
	S80 ~ S64
B0 S127~S96 * S112~S96 * *	
C0 S31 ~ S00 S31 ~ S00 S31 ~ S00	
D0 S63 ~ S32 S63 ~ S32 S63 ~ S32	(COM7
	S80 ~ S64
F0 S127 ~ S96 * S112 ~ S96 * *	
00 S31 ~ S00 S31 ~ S00 S31 ~ S00	
10 S63 ~ S32 S63 ~ S32 S63 ~ S32 S63 ~	COMO
	S80 ~ S64
30 3127~390 3112~390	
00 S31 ~ S00 S31 ~ S00 S31 ~ S00	
50 S63 ~ S32 S63 ~ S32 S63 ~ S32 S63 ~ S32	——————————————————————————————————————
	S80 ~ S64
3 70 5127 570	000
80 S31 ~ S00 S31 ~ S00 S31 ~ S00 S31 ~ S00	
90 S63 ~ S32 S63	$\frac{832}{880 \sim 864}$ COM10
B0 S127 ~ S96 * S112 ~ S96 * * C0 S31 ~ S00 S31 ~ S00 S31 ~ S00 S31 ~ S00	
D0 S63 ~ S32 S63 ~ S32 S63 ~ S32 S63 ~ S32	
	S80 ~ S64 COM11
F0 S127 ~ S96 * S112 ~ S96 * *	
00 S31 ~ S00 S31 ~ S00 S31 ~ S00 S31 ~ S00	
10 S63 ~ S32 S63 ~ S32 S63 ~ S32 S63 ~ S32	, S32
	S80 ~ S64 COM12
30 S127 ~ S96 * S112 ~ S96 * *	
40 S31 ~ S00 S31 ~ S00 S31 ~ S00 S31 ~ S00	- S00
50 S63 ~ S32 S63 ~ S32 S63 ~ S32 S63 ~ S32	. \$32
	$\frac{\text{S32}}{\text{S80} \sim \text{S64}}$ COM13
70 S127~S96 * S112~S96 * *	
4 80 S31 ~ S00 S31 ~ S00 S31 ~ S00 S31 ~ S00	- S00
90 S63 ~ S32 S63 ~ S32 S63 ~ S32 S63 ~ S32	. \$32
	$\frac{1332}{880 \sim 864}$ COM14
B0 S127 ~ S96 * S112 ~ S96 * *	:
C0 S31 ~ S00 S31 ~ S00 S31 ~ S00	- S00
D0 S63 ~ S32 S63 ~ S32 S63 ~ S32 S63 ~	- S32
E0 S95 ~ S64 S95 ~ S64 *	S80 ~ S64 COM15
F0 S127 ~ S96 * S112 ~ S96 * *	
5 00 S31~S00 S31~S00 S31~S00 S31~	- S00
10 S63 ~ S32 S63 ~ S32 S63 ~ S32 S63 ~	- S32
20 S95 ~ S64 S95 ~ S64 *	S80 ~ S64 COM16
30 S127 ~ S96 * S112 ~ S96 * *	





		32x128	48x112	64x96	80x80	
Page		F 0	F 0	F 0	F 0	
	40	S31 ~ S00	S31 ~ S00	S31 ~ S00	S31 ~ S00	
	50	S63 ~ S32	S63 ~ S32	S63 ~ S32	S63 ~ S32	COM17
	60	S95 ~ S64	S95 ~ S64	S95 ~ S64	* S80 ~ S64	COMIT
	70	S127 ~ S96	* S112 ~ S96	*	*	
	80	S31 ~ S00	S31 ~ S00	S31 ~ S00	S31 ~ S00	
	90	S63 ~ S32	S63 ~ S32	S63 ~ S32	S63 ~ S32	COM18
	A0	S95 ~ S64	S95 ~ S64	S95 ~ S64	* S80 ~ S64	COMITO
	В0	S127 ~ S96	* S112 ~ S96	*	*	
	C0	S31 ~ S00	S31 ~ S00	S31 ~ S00	S31 ~ S00	
	D0	S63 ~ S32	S63 ~ S32	S63 ~ S32	S63 ~ S32	COM19
	E0	S95 ~ S64	S95 ~ S64	S95 ~ S64	* S80 ~ S64	COMIT
	F0	S127 ~ S96	* S112 ~ S96	*	*	
	00	S31 ~ S00	S31 ~ S00	S31 ~ S00	S31 ~ S00	
	10	S63 ~ S32	S63 ~ S32	S63 ~ S32	S63 ~ S32	COM20
	20	S95 ~ S64	S95 ~ S64	S95 ~ S64	* S80 ~ S64	001/120
	30	S127 ~ S96	* S112 ~ S96	*	*	
	40	S31 ~ S00	S31 ~ S00	S31 ~ S00	S31 ~ S00	
	50	S63 ~ S32	S63 ~ S32	S63 ~ S32	S63 ~ S32	COM21
	60	S95 ~ S64	S95 ~ S64	S95 ~ S64	* S80 ~ S64	
6	70	S127 ~ S96	* S112 ~ S96	*		
	80	S31 ~ S00	S31 ~ S00	S31 ~ S00	S31 ~ S00	
	90	S63 ~ S32	S63 ~ S32	S63 ~ S32	S63 ~ S32	COM22
	A0	S95 ~ S64	\$95 ~ \$64 * \$112 ~ \$96	S95 ~ S64 *	* \$80 ~ \$64	
	B0	S127 ~ S96	3112 370		G21 G00	
	C0	S31 ~ S00	S31 ~ S00	S31 ~ S00	S31 ~ S00	
	D0 E0	S63 ~ S32	\$63 ~ \$32	S63 ~ S32	\$63 ~ \$32 * \$80 ~ \$64	COM23
	F0	S95 ~ S64	\$95 ~ \$64 * \$112 ~ \$96	\$95 ~ \$64 *	*	
	00	S127 ~ S96 S31 ~ S00	S31 ~ S00	S31 ~ S00	S31 ~ S00	
	10	S63 ~ S32	S63 ~ S32	S63 ~ S32	S63 ~ S32	
	20	S95 ~ S64	S95 ~ S64	S95 ~ S64	* S80 ~ S64	COM24
	30	S127 ~ S96	* S112 ~ S96	*	*	
	40	S31 ~ S00	S31 ~ S00	S31 ~ S00	S31 ~ S00	
	50	S63 ~ S32	S63 ~ S32	S63 ~ S32	S63 ~ S32	
	60	S95 ~ S64	S95 ~ S64	S95 ~ S64	* S80 ~ S64	COM25
	70	S127 ~ S96	* S112 ~ S96	*	*	
7	80	S31 ~ S00	S31 ~ S00	S31 ~ S00	S31 ~ S00	
	90	S63 ~ S32	S63 ~ S32	S63 ~ S32	S63 ~ S32	003.666
	A0	S95 ~ S64	S95 ~ S64	S95 ~ S64	* S80 ~ S64	COM26
	В0	S127 ~ S96	* S112 ~ S96	*	*	
	C0	S31 ~ S00	S31 ~ S00	S31 ~ S00	S31 ~ S00	
	D0	S63 ~ S32	S63 ~ S32	S63 ~ S32	S63 ~ S32	COMOZ
	E0	S95 ~ S64	S95 ~ S64	S95 ~ S64	* S80 ~ S64	COM27
	F0	S127 ~ S96	* S112 ~ S96	*	*	
8	00	S31 ~ S00	S31 ~ S00	S31 ~ S00	S31 ~ S00	
	10	S63 ~ S32	S63 ~ S32	S63 ~ S32	S63 ~ S32	COM28
	20	S95 ~ S64	S95 ~ S64	S95 ~ S64	* S80 ~ S64	COIVIZO
	30	S127 ~ S96	* S112 ~ S96	*	*	
	40	S31 ~ S00	S31 ~ S00	S31 ~ S00	S31 ~ S00	
	50	S63 ~ S32	S63 ~ S32	S63 ~ S32	S63 ~ S32	COM29
	60	S95 ~ S64	S95 ~ S64	S95 ~ S64	* S80 ~ S64	COIVIZA
	70	S127 ~ S96	* S112 ~ S96	*	*	
	80	S31 ~ S00	S31 ~ S00	S31 ~ S00	S31 ~ S00	COM30
	90	S63 ~ S32	S63 ~ S32	S63 ~ S32	S63 ~ S32	
	A0	S95 ~ S64	S95 ~ S64	S95 ~ S64	* S80 ~ S64	





		32x128	48x112	64x96	80x80	
Page		F 0	F 0	F 0	F 0	
	В0	S127 ~ S96	* S112 ~ S96	*	*	
	C0	S31 ~ S00	S31 ~ S00	S31 ~ S00	S31 ~ S00	
	D0	S63 ~ S32	S63 ~ S32	S63 ~ S32	S63 ~ S32	COM31
	E0	S95 ~ S64	S95 ~ S64	S95 ~ S64	* S80 ~ S64	COMST
	F0	S127 ~ S96	* S112 ~ S96	*	*	
	00	*	S31 ~ S00	S31 ~ S00	S31 ~ S00	
	10		S63 ~ S32	S63 ~ S32	S63 ~ S32	COM32
	20		S95 ~ S64	S95 ~ S64	* S80 ~ S64	
	30		* S112 ~ S96	*	*	
	40		S31 ~ S00	S31 ~ S00	S31 ~ S00	
	50		S63 ~ S32	S63 ~ S32	\$63 ~ \$32	COM33
	60 70		\$95 ~ \$64 * \$112 ~ \$96	\$95 ~ \$64 *	* S80 ~ S64	
9	80		S31 ~ S00	S31 ~ S00	S31 ~ S00	
	90		S63 ~ S32	S63 ~ S32	S63 ~ S32	
	A0		\$95 ~ \$64	\$95 ~ \$64	S80 ~ S64	COM34
	B0		* S112 ~ S96	*	*	
	C0		S31 ~ S00	S31 ~ S00	S31 ~ S00	
	D0		S63 ~ S32	S63 ~ S32	S63 ~ S32	
	E0		S95 ~ S64	S95 ~ S64	* S80 ~ S64	COM35
	F0		* S112 ~ S96	*	*	
	00		S31 ~ S00	S31 ~ S00	S31 ~ S00	
	10		S63 ~ S32	S63 ~ S32	S63 ~ S32	G01.62.6
	20		S95 ~ S64	S95 ~ S64	* S80 ~ S64	COM36
	30		* S112 ~ S96	*	*	
	40		S31 ~ S00	S31 ~ S00	S31 ~ S00	
	50		S63 ~ S32	S63 ~ S32	S63 ~ S32	COM37
	60		S95 ~ S64	S95 ~ S64	* S80 ~ S64	COM5/
Α	70		* S112 ~ S96	*	*	
Λ	80		S31 ~ S00	S31 ~ S00	S31 ~ S00	
	90		S63 ~ S32	S63 ~ S32	S63 ~ S32	COM38
	A0		S95 ~ S64	S95 ~ S64	* S80 ~ S64	0011130
	В0		* S112 ~ S96	*	*	
	C0		S31 ~ S00	S31 ~ S00	S31 ~ S00	
	D0		S63 ~ S32	S63 ~ S32	S63 ~ S32	COM39
	E0		\$95 ~ \$64	S95 ~ S64 *	* S80 ~ S64	
	F0		* S112 ~ S96			
	10	-	S31 ~ S00	S31 ~ S00	S31 ~ S00	
	10	-	\$63 ~ \$32	\$63 ~ \$32	\$63 ~ \$32 * \$80 ~ \$64	COM40
	30	-	\$95 ~ \$64 * \$112 ~ \$96	\$95 ~ \$64 *	* 580 ~ 504	
	40	-	S31 ~ S00	S31 ~ S00	S31 ~ S00	
	50		S63 ~ S32	S63 ~ S32	S63 ~ S32	
	60		S95 ~ S64	S95 ~ S64	* S80 ~ S64	COM41
	70		* S112 ~ S96	*	*	
В	80	1	S31 ~ S00	S31 ~ S00	S31 ~ S00	
	90	1	S63 ~ S32	S63 ~ S32	S63 ~ S32	001515
	A0	1	S95 ~ S64	S95 ~ S64	* S80 ~ S64	COM42
	В0	1	* S112 ~ S96	*	*	
	C0	1	S31 ~ S00	S31 ~ S00	S31 ~ S00	
	D0	1	S63 ~ S32	S63 ~ S32	S63 ~ S32	COM42
	E0		S95 ~ S64	S95 ~ S64	* S80 ~ S64	COM43
	F0		* S112 ~ S96	*	*	
С	00		S31 ~ S00	S31 ~ S00	S31 ~ S00	COM44
	10		S63 ~ S32	S63 ~ S32	S63 ~ S32	





		32x128		48x	:112	64x96		80:	x80	
Page			0	F	0	F	0	F	0	
	20			S95 -	~ S64	S95 ~ S64		*	S80 ~ S64	
	30			*	S112 ~ S96	*			*	
	40			S31 -	~ S00	$S31 \sim S00$		S31 -	~ S00	
	50			S63 -	~ S32	S63 ~ S32			~ S32	COM45
	60				~ S64	S95 ~ S64			S80 ~ S64	COMAS
	70				S112 ~ S96	*			*	
	80				~ S00	S31 ~ S00			~ S00	
	90				~ S32	S63 ~ S32			~ S32	COM46
	A0				~ S64	S95 ~ S64 *			\$80 ~ \$64	
	B0				S112 ~ S96					
	C0 D0				~ S00 ~ S32	S31 ~ S00 S63 ~ S32			~ S00 ~ S32	
	E0				~ S64	\$65 ~ \$64			S80 ~ S64	COM47
	F0				S112 ~ S96	*			*	
	00	-			*	S31 ~ S00		S31 /	~ S00	
	10	1				S63 ~ S32			~ S32	
	20	1				S95 ~ S64			S80 ~ S64	COM48
	30	1				*			*	
	40					S31 ~ S00		S31 -	~ S00	
	50					S63 ~ S32			~ S32	COM40
	60					S95 ~ S64		*	S80 ~ S64	COM49
D	70					*		:	*	
D	80					S31 ~ S00		S31 -	~ S00	
	90					S63 ~ S32			~ S32	COM50
	A0					S95 ~ S64		*	S80 ~ S64	COMISO
	В0					*		:	*	
	C0					S31 ~ S00			~ S00	
	D0					S63 ~ S32			~ S32	COM51
	E0					S95 ~ S64			S80 ~ S64	
	F0					*			*	
	00					S31 ~ S00			~ S00	
	10 20					S63 ~ S32 S95 ~ S64		*	~ S32 S80 ~ S64	COM52
	30					393 ~ 304 *			*	
	40					S31 ~ S00			~ S00	
	50	-				S63 ~ S32			~ S32	
	60					S95 ~ S64		*	S80 ~ S64	COM53
_	70					*			*	
Е	80	1				S31 ~ S00		S31 -	~ S00	
	90	1				S63 ~ S32			~ S32	CON 47.4
	A0	1				S95 ~ S64		*	S80 ~ S64	COM54
	В0					*			*	
	C0					S31 ~ S00		S31 -	~ S00	
	D0					S63 ~ S32		S63	~ S32	COM55
	E0					S95 ~ S64		*	S80 ~ S64	COMISS
	F0					*			*	
F	00					S31 ~ S00			~ S00	
	10					S63 ~ S32			~ S32	COM56
	20	-				\$95 ~ \$64 *		*	\$80 ~ \$64	
	30	-								
	40	-				S31 ~ S00			~ S00	
	50 60	-				S63 ~ S32 S95 ~ S64		* S63	~ S32 S80 ~ S64	COM57
	70	1				895 ~ 864 *			* S80 ~ S64	
	80	-				S31 ~ S00			~ S00	COM58
	6 U					331 ~ 300		331	- 500	COMIS





			32x128			48x112		64x96	802	x80	
Page		F		0	F		0	F 0	F	0	
	90							S63 ~ S32	S63 -	~ S32	
	A0							S95 ~ S64	*	S80 ~ S64	
	B0							*		*	
	C0							S31 ~ S00		~ S00	
	D0							S63 ~ S32	* S63 ×	~ S32	COM59
	E0 F0							\$95 ~ \$64 *		\$80 ~ \$64	
	00							S31 ~ S00		~ S00	
	10							S63 ~ S32		~ S32	
	20							S95 ~ S64	*	S80 ~ S64	COM60
	30							*	:	*	
	40							S31 ~ S00	S31 -	~ S00	
	50							S63 ~ S32		~ S32	COM61
	60							S95 ~ S64		S80 ~ S64	COMO
10	70							*		*	
	80							S31 ~ S00		~ S00	
	90							S63 ~ S32	* S63 -	~ S32	COM62
	A0							S95 ~ S64		\$80 ~ \$64	
	B0 C0							S31 ~ S00		~ S00	
	D0							S63 ~ S32		~ S32	
	E0							S95 ~ S64	*	S80 ~ S64	COM63
	F0							*	:	*	
	00								S31 -	~ S00	
	10								S63 -	~ S32	COM64
	20								*	S80 ~ S64	COMO
	30									*	
	40									~ S00	
	50								* S63 -	~ S32	COM65
	60									\$80 ~ \$64	
11	70 80									~ S00	
	90									~ S32	
	A0								*	S80 ~ S64	COM66
	B0								:	*	
	C0								S31 -	~ S00	
	D0								S63 -	~ S32	COM67
	E0								*	S80 ~ S64	COMO
	F0									*	
	00									~ S00	
	10								* S63 -	~ S32	COM68
	20									\$80 ~ \$64	
	30 40									* ~ S00	
	50									~ S32	
	60								*	S80 ~ S64	COM69
1.0	70								;	*	
12	80								S31 -	~ S00	
	90								S63 -	~ S32	COM70
	A0								*	S80 ~ S64	COM70
	В0									*	
	C0									~ S00	
	D0									~ S32	COM71
	E0								*	\$80 ~ \$64	- , -
	F0								,	T	





		32x128	48x112	64x96	80x80	
Page		F 0		F 0	F 0	
	00				S31 ~ S00	
	10				S63 ~ S32	COM72
	20				* S80 ~ S64	COM72
	30				*	
	40				S31 ~ S00	
	50				S63 ~ S32	COM73
	60				* S80 ~ S64	COM1/3
13	70				*	
13	80				S31 ~ S00	
	90				S63 ~ S32	COM74
	A0				* S80 ~ S64	COM74
	В0				*	
	C0				S31 ~ S00	
	D0				S63 ~ S32	COM75
	E0				* S80 ~ S64	0011175
	F0				*	
	00				S31 ~ S00	
	10				S63 ~ S32	COM76
	20				* S80 ~ S64	
	30					
	40				S31 ~ S00	
	50				\$63 ~ \$32 * \$80 ~ \$64	COM77
	60				* S80 ~ S64	
14	70					
	80				S31 ~ S00	
	90 A0				\$63 ~ \$32 * \$80 ~ \$64	COM78
					* S80 ~ S64 *	
	B0 C0				S31 ~ S00	
	D0				\$63 ~ \$32	
					* S80 ~ S64	COM79
	E0 F0				* \$80 ~ \$64	
	10				T	

8.2. 4 Gray Scale LCD Display RAM Map

Page		32x128		48x112	64:	x96	80x80		
		F 0	F	0	F	0	F	0	
	00	S63 ~ S00	S63 ~ S00		S63 -	~ S00	S63 ~ S00		COM0
	10	S127 ~ S64	*	S112~ S64	*	S96 ~ S64	*	S80~ S64	COMO
	20	S63 ~ S00		$S63 \sim S00$	S63 -	~ S00	S63 ~ S00		COM1
	30	S127 ~ S64	*	S112~ S64	*	S96 ~ S64	*	S80~ S64	COMI
	40	S63 ~ S00		S63 ~ S00	S63 -	~ S00	S63 ~ S00		COM2
	50	S127 ~ S64	*	S112~ S64	*	S96 ~ S64	*	S80~ S64	COMZ
	60	S63 ~ S00	S63 ~ S00		S63 -	~ S00	S63 ~ S00		COM3
1	70	S127 ~ S64	*	S112~ S64	*	S96 ~ S64	*	S80~ S64	COMS
1	80	S63 ~ S00	S63 ~ S00		S63 -	~ S00	S63 ~ S00		COM4
	90	S127 ~ S64	*	S112~ S64	*	S96 ~ S64	*	S80~ S64	COM4
	A0	S63 ~ S00		S63 ~ S00	S63 -	~ S00	S63 ~ S00		COM5
	В0	S127 ~ S64	*	S112~ S64	*	S96 ~ S64	*	S80~ S64	COMS
	C0	S63 ~ S00		S63 ~ S00	S63 -	~ S00	S63 ~ S00		COM6
	D0	S127 ~ S64	*	S112~ S64	*	S96 ~ S64	*	S80~ S64	COMO
	E0	S63 ~ S00		S63 ~ S00	S63	~ S00	S63 ~ S00		COM7
	F0	S127 ~ S64	*	S112~ S64	*	S96 ~ S64	*	S80~ S64	COMI





Page		32x128		48x112	642	x96	80x80		
		F 0	F	0	F	0	F	0	
	00	S63 ~ S00		S63 ~ S00	S63 -	~ S00	S63 ~ S00	_	COM8
	10	S127 ~ S64	*	S112~ S64	*	S96 ~ S64	*	S80~ S64	COM6
	20	S63 ~ S00		$S63 \sim S00$	S63 -	~ S00	S63 ~ S00		COM9
	30	S127 ~ S64	*	S112~ S64	*	S96 ~ S64	*	S80~ S64	COM
	40	S63 ~ S00		$S63 \sim S00$	S63 -	~ S00	S63 ~ S00		COM10
	50	S127 ~ S64	*	S112~ S64	*	S96 ~ S64	*	S80~ S64	COMITO
	60	S63 ~ S00		S63 ~ S00	S63 -	~ S00	S63 ~ S00		COM11
2	70	S127 ~ S64	*	S112~ S64	*	S96 ~ S64	*	S80~ S64	COMIT
2	80	S63 ~ S00		$S63 \sim S00$	S63 -	~ S00	S63 ~ S00		COM12
	90	S127 ~ S64	*	S112~ S64	*	S96 ~ S64	*	S80~ S64	COM12
	A0	S63 ~ S00		$S63 \sim S00$	S63 -	~ S00	S63 ~ S00		COM13
	В0	S127 ~ S64	*	S112~ S64	*	S96 ~ S64	*	S80~ S64	COMITS
	C0	S63 ~ S00		S63 ~ S00	S63 -	~ S00	S63 ~ S00		COM14
	D0	S127 ~ S64	*	S112~ S64	*	S96 ~ S64	*	S80~ S64	COM14
	E0	S63 ~ S00		S63 ~ S00	S63 -	~ S00	S63 ~ S00	_	COM15
	F0	S127 ~ S64	*	S112~ S64	*	S96 ~ S64	*	S80~ S64	COMITS
	00	S63 ~ S00		S63 ~ S00	S63 -	~ S00	S63 ~ S00		COM16
	10	S127 ~ S64	*	S112~ S64	*	S96 ~ S64	*	S80~ S64	COM16
	20	S63 ~ S00		S63 ~ S00	S63 -	~ S00	S63 ~ S00		COM17
	30	S127 ~ S64	*	S112~ S64	*	S96 ~ S64	*	S80~ S64	COM17
	40	S63 ~ S00		S63 ~ S00	S63 -	~ S00	S63 ~ S00		COM10
	50	S127 ~ S64	*	S112~ S64	*	S96 ~ S64	*	S80~ S64	COM18
	60	S63 ~ S00		S63 ~ S00	S63 -	~ S00	S63 ~ S00		COM10
,	70	S127 ~ S64	*	S112~ S64	*	S96 ~ S64	*	S80~ S64	COM19
3	80	S63 ~ S00		S63 ~ S00	S63 -	~ S00	S63 ~ S00		COM20
	90	S127 ~ S64	*	S112~ S64	*	S96 ~ S64	*	S80~ S64	COM20
	A0	S63 ~ S00		S63 ~ S00	S63 -	~ S00	S63 ~ S00		COMO
	В0	S127 ~ S64	*	S112~ S64	*	S96 ~ S64	*	S80~ S64	COM21
	C0	S63 ~ S00		S63 ~ S00	S63 -	~ S00	S63 ~ S00		COMO
	D0	S127 ~ S64	*	S112~ S64	*	S96 ~ S64	*	S80~ S64	COM22
	E0	S63 ~ S00		S63 ~ S00	S63 -	~ S00	S63 ~ S00		COMO
	F0	S127 ~ S64	*	S112~ S64	*	S96 ~ S64	*	S80~ S64	COM23
	00	S63 ~ S00		S63 ~ S00	S63 -	~ S00	S63 ~ S00		COM24
	10	S127 ~ S64	*	S112~ S64	*	S96 ~ S64	*	S80~ S64	COM24
	20	S63 ~ S00		S63 ~ S00	S63 -	~ S00	S63 ~ S00		COM25
	30	S127 ~ S64	*	S112~ S64	*	S96 ~ S64	*	S80~ S64	COMIZS
	40	S63 ~ S00		S63 ~ S00	S63 -	~ S00	S63 ~ S00		COM26
	50	S127 ~ S64	*	S112~ S64	*	S96 ~ S64	*	S80~ S64	COM26
	60	S63 ~ S00		S63 ~ S00	S63 -	~ S00	S63 ~ S00		COM27
1	70	S127 ~ S64	*	S112~ S64	*	S96 ~ S64	*	S80~ S64	COM27
4	80	S63 ~ S00		S63 ~ S00	S63 -	~ S00	S63 ~ S00		COM28
	90	S127 ~ S64	*	S112~ S64	*	S96 ~ S64	*	S80~ S64	COMIZA
	A0	S63 ~ S00		S63 ~ S00	S63 -	~ S00	S63 ~ S00		COM29
	В0	S127 ~ S64	*	S112~ S64	*	S96 ~ S64	*	S80~ S64	
	C0	S63 ~ S00		S63 ~ S00	S63 -	~ S00	S63 ~ S00		COM30
	D0	S127 ~ S64	*	S112~ S64	*	S96 ~ S64	*	S80~ S64	COMISO
	E0	S63 ~ S00		S63 ~ S00	S63 -	~ S00	S63 ~ S00		COM31
	F0	S127 ~ S64	*	S112~ S64	*	S96 ~ S64	*	S80~ S64	COMIST
5	00	*		S63 ~ S00	S63 -	~ S00	S63 ~ S00		COM32
	10		*	S112~ S64	*	S96 ~ S64	*	S80~ S64	COM132
	20			S63 ~ S00	S63 -	~ S00	S63 ~ S00		COM22
	30		*	S112~ S64	*	S96 ~ S64	*	S80~ S64	COM33
	40			S63 ~ S00	S63 -	~ S00	S63 ~ S00		COM24
	50		*	S112~ S64	*	S96 ~ S64	*	S80~ S64	COM34
	60			S63 ~ S00	S63 -	~ S00	S63 ~ S00		COM35





Page		32x128		48x112	642	x96	80x80		
		F 0	F	0	F	0	F	0	
	70		*	S112~ S64	*	S96 ~ S64	*	S80~ S64	
	80			S63 ~ S00	S63 -	~ S00	S63 ~ S00	ı	COM26
	90		*	S112~ S64	*	S96 ~ S64	*	S80~ S64	COM36
	A0			S63 ~ S00	S63 -	~ S00	S63 ~ S00	•	COM27
	В0		*	S112~ S64	*	S96 ~ S64	*	S80~ S64	COM37
	C0			S63 ~ S00	S63 -	~ S00	S63 ~ S00		COM20
	D0		*	S112~ S64	*	S96 ~ S64	*	S80~ S64	COM38
	E0			S63 ~ S00	S63 -	~ S00	S63 ~ S00		COM20
	F0		*	S112~ S64	*	S96 ~ S64	*	S80~ S64	COM39
	00			S63 ~ S00	S63 -	~ S00	S63 ~ S00		GOM440
	10		*	S112~ S64	*	S96 ~ S64	*	S80~ S64	COM40
	20			S63 ~ S00	S63 -	~ S00	S63 ~ S00		COM41
	30		*	S112~ S64	*	S96 ~ S64	*	S80~ S64	COM41
	40			S63 ~ S00	S63 -	~ S00	S63 ~ S00		GOV442
	50		*	S112~ S64	*	S96 ~ S64	*	S80~ S64	COM42
	60			S63 ~ S00	S63 -	~ S00	S63 ~ S00		GOV 142
	70		*	S112~ S64	*	S96 ~ S64	*	S80~ S64	COM43
6	80	1		S63 ~ S00	S63 -	~ S00	S63 ~ S00	. 507	002444
	90		*	S112~ S64	*	S96 ~ S64	*	S80~ S64	COM44
	A0			S63 ~ S00	S63 -	~ S00	S63 ~ S00	501	G03.545
	В0		*	S112~ S64	*	S96 ~ S64	*	S80~ S64	COM45
	C0			S63 ~ S00	S63 ~	~ S00	S63 ~ S00	501	001111
	D0		*	S112~ S64	*	S96 ~ S64	*	S80~ S64	COM46
	E0			S63 ~ S00	S63 -	~ S00	S63 ~ S00	304	G01.64 5
	F0		*	S112~ S64	*	S96 ~ S64	*	S80~ S64	COM47
	00			*	S63 -	~ S00	S63 ~ S00	304	601.110
	10				*	S96 ~ S64	*	S80~ S64	COM48
	20				S63 -	~ S00	S63 ~ S00	504	601.110
	30				*	S96 ~ S64	*	S80~ S64	COM49
	40				S63 ~	~ S00	S63 ~ S00	504	G01.550
	50				*	S96 ~ S64	*	S80~ S64	COM50
	60				S63 -	~ S00	S63 ~ S00	504	G01.554
1 _ 1	70				*	S96 ~ S64	*	S80~ S64	COM51
7	80				S63 -	~ S00	S63 ~ S00	504	G01.554
	90				*	S96 ~ S64	*	S80~ S64	COM52
	A0				S63 -	~ S00	S63 ~ S00	504	~ ~
	B0				*	S96 ~ S64	*	S80~ S64	COM53
	C0				S63 -	~ S00	S63 ~ S00	304	gor :
	D0				*	S96 ~ S64	*	S80~ S64	COM54
	E0				S63 -	~ S00	S63 ~ S00	304	go: 55-
	F0				*	S96 ~ S64	*	S80~ S64	COM55
8	00				S63 -	~ S00	S63 ~ S00	304	a
	10				*	S96 ~ S64	*	S80~ S64	COM56
	20				S63 -	~ S00	S63 ~ S00	304	g = -
	30				*	S96 ~ S64	*	S80~	COM57
	40				S63 -	~ S00	S63 ~ S00	S64	a
	50				*	S96 ~ S64	*	S80~ S64	COM58
	60				S63 -	~ S00	S63 ~ S00	304	
	70				*	S96 ~ S64	*	S80~	COM59
	80				S63 -	~ S00	S63 ~ S00	S64	
	90				*	S96 ~ S64	*	S80~	COM60
	A0				S63 c	~ S00	S63 ~ S00	S64	
	B0				*	\$96 ~ \$64	*	S80~	COM61
	C0					~ S00	S63 ~ S00	S64	
	D0				*	\$96 ~ \$64	*	S80~	COM62
	טע		l		<u> </u>	570 ~ 504		S64	l





Page		32x128	48x112	64x96	80x80	
		F 0	F 0	F 0	F 0	
	E0			S63 ~ S00	S63 ~ S00	COM62
	F0			* \$96 ~ \$64	* S80~ S64	COM63
	00				S63 ~ S00	COM64
	10				* S80~ S64	COM64
	20				S63 ~ S00	COM65
	30				* S80~ S64	COMOS
	40				S63 ~ S00	COM66
	50				* S80~ S64	COM66
	60				S63 ~ S00	COMCZ
9	70				* S80~ S64	COM67
9	80				S63 ~ S00	COMCO
	90				* S80~ S64	COM68
	A0				S63 ~ S00	COMO
	В0				* S80~ S64	COM69
	C0				S63 ~ S00	COM70
	D0				* S80~ S64	COM70
	E0				S63 ~ S00	COM71
	F0			*	* S80~ S64	COM71
	00			T	S63 ~ S00	COM72
	10				* S80~ S64	COM72
	20				S63 ~ S00	COM72
	30				* S80~ S64	COM73
	40				S63 ~ S00	COM74
	50				* S80~ S64	COM74
	60				S63 ~ S00	COM75
	70				* S80~ S64	COM75
Α	80				S63 ~ S00	COM76
	90				* S80~ S64	COM76
	A0				S63 ~ S00	COM77
	В0				* S80~ S64	COM77
	C0				S63 ~ S00	COM79
	D0				* S80~ S64	COM78
	E0				S63 ~ S00	COM70
	F0				* S80~ S64	COM79

8.3. Black and White LCD Display RAM Map

Page		32x	128		48x	:112		64x96		80	x80	
		F	0		F	0	I	7 () F		0	
0	00	S127	~ S00	*	S11	$1 \sim S00$	*	S95 ~ S00	*		S79 ~ S00	COM0
	10	S127	~ S00	*	S11	1 ~ S00	*	S95 ~ S00	*		S79 ~ S00	COM1
	20	S127	~ S00	*	S11	1 ~ S00	*	S95 ~ S00	*		S79 ~ S00	COM2
	30	S127	~ S00	*	S11	$1 \sim S00$	*	S95 ~ S00	*		S79 ~ S00	COM3
	40	S127	~ S00	*	S11	1 ~ S00	*	S95 ~ S00	*		S79 ~ S00	COM4
	50	S127	~ S00	*	S11	1 ~ S00	*	S95 ~ S00	*		S79 ~ S00	COM5
	60	S127	~ S00	*	S11	$1 \sim S00$	*	S95 ~ S00	*		S79 ~ S00	COM6
	70	S127	~ S00	*	S11	$1 \sim S00$	*	S95 ~ S00	*		S79 ~ S00	COM7
	80	S127	~ S00	*	S11	1 ~ S00	*	S95 ~ S00	*		S79 ~ S00	COM8
	90	S127	~ S00	*	S11	$1 \sim S00$	*	S95 ~ S00	*		S79 ~ S00	COM9
	A0	S127	~ S00	*	S11	$1 \sim S00$	*	S95 ~ S00	*		S79 ~ S00	COM10
	В0	S127	~ S00	*	S11	1 ~ S00	*	S95 ~ S00	*		S79 ~ S00	COM11
	C0	S127	~ S00	*	S11	$1 \sim S00$	*	S95 ~ S00	*		S79 ~ S00	COM12
	D0	S127	~ S00	*	S11	1 ~ S00	*	S95 ~ S00	*		$S79 \sim S00$	COM13





Page		32x128		48x112		64x96		80x80	
		F 0		F 0	I	F 0	F	0	
	E0	S127 ~ S00	*	S111 ~ S00	*	S95 ~ S00	*	S79 ~ S00	COM14
	F0	S127 ~ S00	*	S111 ~ S00	*	S95 ~ S00	*	S79 ~ S00	COM15
	00	S127 ~ S00	*	S111 ~ S00	*	S95 ~ S00	*	S79 ~ S00	COM16
	10	S127 ~ S00	*	S111 ~ S00	*	S95 ~ S00	*	S79 ~ S00	COM17
	20	S127 ~ S00	*	S111 ~ S00	*	S95 ~ S00	*	S79 ~ S00	COM18
	30	S127 ~ S00	*	S111 ~ S00	*	S95 ~ S00	*	S79 ~ S00	COM19
	40	S127 ~ S00	*	S111 ~ S00	*	S95 ~ S00	*	S79 ~ S00	COM20
	50	S127 ~ S00	*	S111 ~ S00	*	S95 ~ S00	*	S79 ~ S00	COM21
	60	S127 ~ S00	*	S111 ~ S00	*	S95 ~ S00	*	S79 ~ S00	COM22
1	70	S127 ~ S00	*	S111 ~ S00	*	S95 ~ S00	*	S79 ~ S00	COM23
l	80	S127 ~ S00	*	S111 ~ S00	*	S95 ~ S00	*	S79 ~ S00	COM24
	90	S127 ~ S00	*	S111 ~ S00	*	S95 ~ S00	*	S79 ~ S00	COM25
	A0	S127 ~ S00	*	S111 ~ S00	*	S95 ~ S00	*	S79 ~ S00	COM26
	В0	S127 ~ S00	*	S111 ~ S00	*	S95 ~ S00	*	S79 ~ S00	COM27
	C0	S127 ~ S00	*	S111 ~ S00	*	S95 ~ S00	*	S79 ~ S00	COM28
	D0	S127 ~ S00	*	S111 ~ S00	*	S95 ~ S00	*	S79 ~ S00	COM29
	E0	S127 ~ S00	*	S111 ~ S00	*	S95 ~ S00	*	S79 ~ S00	COM30
	F0	S127 ~ S00	*	S111 ~ S00	*	S95 ~ S00	*	S79 ~ S00	COM31
	00	*	*	S111 ~ S00	*	S95 ~ S00	*	S79 ~ S00	COM32
	10		*	S111 ~ S00	*	S95 ~ S00	*	S79 ~ S00	COM33
	20		*	S111 ~ S00	*	S95 ~ S00	*	S79 ~ S00	COM34
	30		*	S111 ~ S00	*	S95 ~ S00	*	S79 ~ S00	COM35
	40		*	S111 ~ S00	*	S95 ~ S00	*	S79 ~ S00	COM36
	50		*	S111 ~ S00	*	S95 ~ S00	*	S79 ~ S00	COM37
	60		*	S111 ~ S00	*	S95 ~ S00	*	S79 ~ S00	COM38
	70		*	S111 ~ S00	*	S95 ~ S00	*	S79 ~ S00	COM39
2	80		*	S111 ~ S00	*	S95 ~ S00	*	S79 ~ S00	COM40
	90		*	S111 ~ S00	*	S95 ~ S00	*	S79 ~ S00	COM41
	A0		*	S111 ~ S00	*	S95 ~ S00	*	S79 ~ S00	COM42
	В0		*	S111 ~ S00	*	S95 ~ S00	*	S79 ~ S00	COM43
	C0		*	S111 ~ S00	*	S95 ~ S00	*	S79 ~ S00	COM44
	D0		*	S111 ~ S00	*	S95 ~ S00	*	S79 ~ S00	COM45
	E0		*	S111 ~ S00	*	S95 ~ S00	*	S79 ~ S00	COM46
	F0		*	S111 ~ S00	*	S95 ~ S00	*	S79 ~ S00	COM47
	00			*	*	S95 ~ S00	*	S79 ~ S00	COM48
	10				*	S95 ~ S00	*	S79 ~ S00	COM49
	20				*	S95 ~ S00	*	S79 ~ S00	COM50
	30				*	S95 ~ S00	*	S79 ~ S00	COM51
	40				*	S95 ~ S00	*	S79 ~ S00	COM52
	50				*	S95 ~ S00	*	S79 ~ S00	COM53
	60				*	S95 ~ S00	*	S79 ~ S00	COM54
2	70				*	S95 ~ S00	*	S79 ~ S00	COM55
3	80				*	S95 ~ S00	*	S79 ~ S00	COM56
	90				*	S95 ~ S00	*	S79 ~ S00	COM57
	A0				*	S95 ~ S00	*	S79 ~ S00	COM58
	В0				*	S95 ~ S00	*	S79 ~ S00	COM59
	C0				*	S95 ~ S00	*	S79 ~ S00	COM60
	D0				*	S95 ~ S00	*	S79 ~ S00	COM61
	E0				*	S95 ~ S00	*	S79 ~ S00	COM62
	F0				*	S95 ~ S00	*	S79 ~ S00	COM63
4	00					*	*	S79 ~ S00	COM64
	10						*	S79 ~ S00	COM65
	20						*	S79 ~ S00	COM66
	30						*	S79 ~ S00	COM67
	40						*	S79 ~ S00	COM68





Page		32x	128	48x	112	642	x96	80)x80	
		F	0	F	0	F	0	F	0	
	50							*	S79 ~ S00	COM69
	60							*	$S79 \sim S00$	COM70
	70							*	$S79 \sim S00$	COM71
	80							*	$S79 \sim S00$	COM72
	90							*	$S79 \sim S00$	COM73
	A0							*	$S79 \sim S00$	COM74
	B0							*	$S79 \sim S00$	COM75
	C0							*	$S79 \sim S00$	COM76
	D0							*	$S79 \sim S00$	COM77
	E0							*	S79 ~ S00	COM78
	F0							*	$S79 \sim S00$	COM79



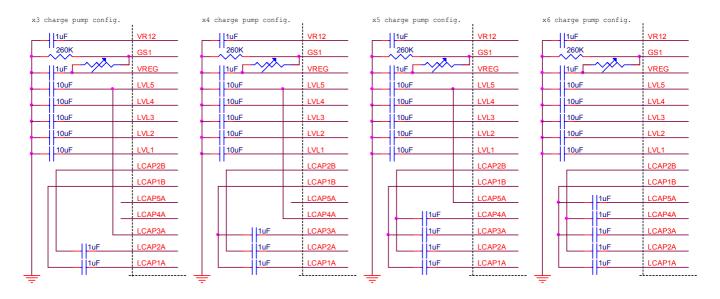


9. LCD Power Supply

The built-in LCD power supply is equipped with input voltage regulator, voltage multiplier and bias voltage generating circuit with active buffer instead of passive resistor voltage dividing network. The input voltage is regulated to LVREG using the internally generated LVAG as reference voltage. LVREG can be adjusted by resistors between LGS1 and LVREG.

LVREG adjustment guideline: First, the level of LVREG must be at least 0.4 volt lower than VDD at all time, even at the end of battery life, for the regulator to function properly. For example, if the VDD is expected to drop to 2.2 volts when battery is low, then the level of LVREG can only be set at 1.8 volts max. With this constraint, it is advisable to set the level of LVREG as high as possible and use less charge pump stages to save power. For example, to pump the 2 volts to 12 volts requires 6 charge pump stages; to pump the 2.4 volts to 12 volts requires only 5 charge pump stages which consumes less power. So it is recommended not to adjust the LVREG to an unnecessary low level.

Voltage charge pump: The LVREG is then multiplied by 3, 4, 5, or 6 times, depending on external capacitors configurations as shown below, to generate LVL5. Please note that LVL5 must be lower than 12 volts to prevent chip from break-down. The capacitance of capacitors connected to LVL1~5 shall be increased in an appropriate amount based on the LCD panel size. For small size LCD panel, the 10uF capacitors are enough, but 22uF capacitors may be necessary for large LCD size application.



The internal reference voltage has built-in temperature compensation to make up the reference voltage deviation due to the temperature variation. Four temperature coefficients are available for selection by mask option MO_TC. It's used to compensate the LCD display feature in the range of room temperature to low temperature. User shall set the MO_TC value based on the LCD feature and operation environment. If the MO_TC is set to "11", the LCD power voltage will have 0.33% decrease when the temperature increases one degree.





MO_TC	Temp. Coef.
00	-0.0 %/°C
01	-0.16 %/°C
10	-0.22 %/°C
11	-0.33 %/°C

Heavy LCD load: The bias voltages LVL1 ~ LVL5 for LCD driver are generated from internal bias network and buffered with active drive to provide greater bias driving strength. Usually larger LCD panel needs more power to drive. Four driving capabilities, which can be selected by mask option, are provided to suit the needs of application. Please note that high driving capability will cause the power consumption to be increased.

MO_LOAD	Driving Current
00	Low
01	Medium
10	Medium high
11	High

External LCD power supply: If the maximal driving option is still inadequate for applications, user may choose to use the external LCD power supply. In that case, there are still several options:

First, use the internal regulator and charge pump circuit to generate the high voltage, but use external bias network to generate and supply the bias voltage level LVL1 \sim LVL5. In this case, the buffered active drive for internal bias needs to be turned off to avoid confliction with external bias circuit and DC current drain.

The second option is to turn off internal charge pump circuit, and use external DC-to-DC circuit to generate high voltage and use internal bias network and buffer active drive to generate bias voltages.

The third option is to turn off internal regulator, charge pump circuit, and bias buffer circuit and use external circuit to generate the high voltage and bias voltage. The individual circuit can be turned on or off by the appropriate bit in LCDC and LCDPS registers and MO PUMPE mask option.

Configuration	MO_PUMPE	BUFE	Internal Charge pump	Internal Bias Buffer
External charge-pump/External bias circuit	0	0	×	×
External charge-pump/Internal bias circuit	0	1	×	✓
Internal charge-pump/ External bias circuit	1	0	✓	×
Internal charge-pump/Internal bias circuit	1	1	✓	✓

Address	NAME		Field								RESET
0FH	LCDC	-	-	CLR_GP	Reserved			BLANK	LCDE	W	1x xx10
24H	LCDPS	-	-	-	-	-	POWDN	PAcc	BUFE	R/W	100





Field	Value	Function
POWDN	0	LCD power system enabled.
FOWDIN	1	LCD power system disabled.
PAcc	0	Internal Charge-pump doesn't accelerate to charge the capacitor.
PACC	1	Internal Charge-pump accelerates to charge the capacitor.
BUFE	0	Disable internal bias network buffer
BULE	1	Enable internal bias network buffer
CLR GP	0	Reset GRAY palette register pointer by write '0' to CLR_P bit.
CLK_GF	1	No effect on GRAY palette register pointer
	0	normal display
BLANK	1	LCD display blanked. The COM signals of LCD driver output inactive levels
	1	(LVL4 and LVL1) while SEG signals output normal display patterns.
	0	LCD driver disabled, LCD driver has no output signal and LVL1 ~ LVL5 is pulled
LCDE	U	up to VDD
	1	LCD driver master control enabled

Bias Setting: Different duties require different bias settings. There is some theoretical correspondence between the Duty and Bias Setting. However, it is better to use it as starting point and adjust it with real LCD panel connected to it to determine the final setting. The theoretic relationship between the duty and bias setting is as the following table: However, the actual bias setting should be determined based on the best visual effect given when the target LCD panel is connected.

Duty Cycle	Normal Bias Setting
32 duty	1/7
48 duty	1/8
64 duty	1/9
80 duty	1/10

The bias setting is made by mask option MO_LBSR[1..0].

MO_LBSR[10]	Bias Setting
00	1/7
01	1/8
10	1/9
11	1/10

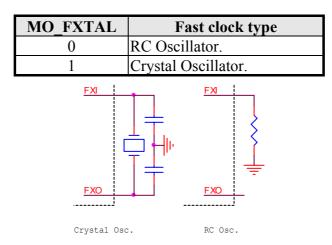
Please note that LCD driver must be turned off before the IC goes into sleep mode. That means user must clear the bit 0 of LCDC to turn off LCD driving circuit before setting bit6 of OP1 to enter sleep mode. Large current might happen if the procedure is not followed. Please note that LCD driver uses slow clock as clock source. The LCD display will not display normally if it works in Fast clock only mode because the LCD refresh action is too fast. The LCD power system shall be enabled by set POWDN to '1' before the LCD display is enabled. In order to accelerate the capacitor charging, the "PAcc" bit shall be set when the LCD power system is initialized and then "PAcc" can be cleared when the LCD power system is stable.





10. Oscillators

The MCU is equipped with two clock sources with a variety of selections on the types of oscillators to choose from. The system designer can select oscillator types based on the cost target, timing accuracy requirements etc. Crystal, Resonator or the RC oscillator can be used as fast clock source, components should be placed as close to the pins as possible. The type of oscillator used is selected by mask option MO_FXTAL.



The RC oscillator has a built-in capacitor. An external resistor is needed to connect from FXI to GND to determine the oscillation frequency. The capacitance of internal RC oscillator is selected by mask option MO_RCAP[2..0].

MO_RCAP[2:0]	Internal RC Cap. (pF)
000	2
001	4
010	7
011	14
100	20
101	40
110	50
111	60

The following table shows the combinations of R and C, and the resulting frequency. Please note that oscillation frequency in the table only represents oscillation frequencies of certain samples. The actual oscillation frequency may vary up to $\pm 15\%$ from lot to lot due to process parameter variations. User must take this into consideration when using this chip in applications.

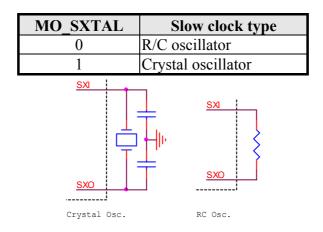




Ring Oscillator Frequency Table

R (ΚΩ)	40	20	14	7	4	2	
30.20	0.8	1.5	2.0	3.0	4.0	5.0	MHz
19.92	1.2	2.2	2.8	4.4	5.6	7.0	MHz
9.98	2.3	4.0	5.1	7.5	•	•	MHz

Two types of oscillator, crystal and RC, can be used as slow clock selectable by mask option MO_SXTAL. If used time keeping function or other applications that required the accurate timing, crystal oscillator is recommended. If the timing accuracy is not important, then RC type oscillator can be used to reduce cost.



With two clock sources available, the system can switch among operation modes of Normal, Slow, Idle, and Sleep modes by the setting of OP1 and OP2 registers as shown in tables below to suit the needs of application such as high speed or low power, etc.

OP1	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
Field	DRDY	STOP	SLOW	INTE	T2E	T1E	Z	C
Mode	R/W							
Reset	1	0	0	0	0	0	-	-

OP2	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
Field	IDLE	PNWK	TCWK	TBE	TBS[30]			
Mode	R/W	R	R	R/W	R/W	R/W	R/W	R/W
Reset	0	-	-	0	-	-	-	-

If the dual clock mode is used, the LCD display, Timer1 and Timer Base will derive its clock source from slow clock while the other blocks will operate with the fast clock.

11. General Purpose I/O

There are two dedicated general purpose I/O ports, PRTC[7..4] and PRTD, while the PRT14, PRT15 and PRT17 are multiplexed with LCD segment driver pins. All the I/O Ports are bi-directional and of non-

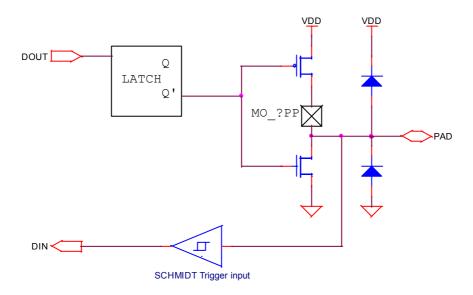




tri-state output structure. The output has weak sourcing (50 μ A) and stronger sinking (1 mA) capability and each can be configured as push-pull or open-drain output structure individually by mask option.

When the I/O port is used as input, the weakly high sourcing can be used as weakly pull-up. Open drain can be used if the pull-up is not required and let the external driver to drive the pin. Please note that a floating pad could cause more power consumption since the noise could interfere with the circuit and cause the input to toggle. A '1' needs to be written to port first before reading the input data from the I/O pin. If the PMOS is used as pull-up, care should be taken to avoid the constant power drain by DC path between pull-up and external circuit.

The input port has built-in Schmidt trigger to prevent it from chattering. Hysteresis level of Schmidt trigger is 1/3 VDD.



As pads of PRT14, PRT15 and PRT17 are shared with LCD segment driver, the function of the pad is determined by mask options. Following table is the setting for MO_LIO?[...] and MO_?PP[...] and others related to LCD display setting and pin assignment features.

MO_LIO?[]	MO_?PP[]	I/O Port	LCD Pin
0	0	Open-drain output	
0	1	Push-pull output	
1	0		XX
1	1		LCD Display

--: Function not available.

xx: Displayable, but may have abnormal leakage current, do not use.





12. Key Scan Circuit

The built-in 4x20 hardware keyboard scan circuit helps to reduce the pin counts where application requires large key matrix and high LCD pixel count as well as the firmware effort. As key-scan pins are shared with LCD segment and PRTC4 ~ PRTC7 pins, it is advisable to put resistors between segment pins and key matrix to avoid shorting the segment pins when two or more keys in the same row are pressed simultaneously. Two key can be detected simultaneously and the first detected key code is stored in KEY0 register and the second in KEY1 register respectively. The key code for each key location is listed in the following table.

Key Loc	SCNI0	SCNI1	SCNI2	SCNI3
SCNO0	0x80	0xA0	0xC0	0xE0
SCNO1	0x81	0xA1	0xC1	0xE1
SCNO2	0x82	0xA2	0xC2	0xE2
SCNO3	0x83	0xA3	0xC3	0xE3
SCNO4	0x84	0xA4	0xC4	0xE4
SCNO5	0x85	0xA5	0xC5	0xE5
SCNO6	0x86	0xA6	0xC6	0xE6
SCNO7	0x87	0xA7	0xC7	0xE7
SCNO8	0x88	0xA8	0xC8	0xE8
SCNO9	0x89	0xA9	0xC9	0xE9
SCNO10	0x8A	0xAA	0xCA	0xEA
SCNO11	0x8B	0xAB	0xCB	0xEB
SCNO12	0x8C	0xAC	0xCC	0xEC
SCNO13	0x8D	0xAD	0xCD	0xED
SCNO14	0x8E	0xAE	0xCE	0xEE
SCNO15	0x8F	0xAF	0xCF	0xEF
SCNO16	0x90	0xB0	0xD0	0xF0
SCNO17	0x91	0xB1	0xD1	0xF1
SCNO18	0x92	0xB2	0xD2	0xF2
SCNO19	0x93	0xB3	0xD3	0xF3

KEY0	BIT7	BIT6	BIT5	BIT4	BIT3	BIT2	BIT1	BIT0
0x22	R	Row	Index		C	olumn Ind	ex	

KEY1	BIT7	BIT6	BIT5	BIT4	BIT3	BIT2	BIT1	BIT0
0x23	-	Row	Index		C	olumn Ind	ex	

The bit 7 of KEY0 and KEY1 is repeat indicator when the same key is scanned for the second time, the R bit will be cleared to indicate the key is not released yet.





The key-scan function can be turned on/off by mask option MO_LCDKEY.

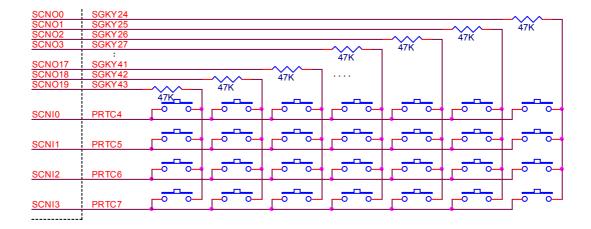
MO_LCDKEY	SGKY[4324] Function
0	as SEG only
1	as SEG as well as KEY_SCAN

The pulse width of key-scan signal can be selected by mask options MO_SNCK[1:0].

MO_SNCK[10]	Key Scan Pulse Width
00	0.5 SCK
01	1.0 SCK
10	1.5 SCK
11	2.0 SCK

The strength of key-scan signal can also be selected by mask options MO_SCDRV[1:0].

MO_SCDRV[10]	Key Scan Signal Strength
00	weakest
01	weak
10	strong
11	strongest





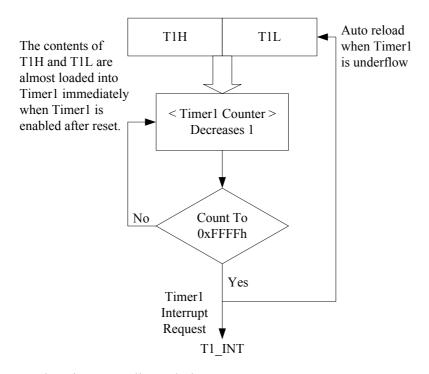


13. Timer1

The Timer1 consists of two 8-bit write-only preload registers T1H and T1L and 16-bit down counter. If Timer1 is enabled, the counter will decrement by one with each incoming clock pulse. Timer1 interrupt will be generated when the counter underflows - counts down to FFFFH. And the counter will be automatically reloaded with the value of T1H and T1L.

The clock source of Timer1 is derived from slow clock "SCK" at dual clock or slow clock only mode. And it comes from the fast clock "FCK" at fast clock only mode.

Please note that the interrupt is generated when counter counts from 0000H to FFFFH. If the value of T1H and T1L is N, and count down to FFFFH, the total count is N+1. The content of counter is zero when system resets. Once it is enabled to count at this moment, interrupt will be generated immediately and value of T1H and T1L will be loaded since it counts to FFFFH. So the T1H and T1L value should be set before enabling Timer1.



The Timer1 related control registers are list as below:

Register	Address	Field	Bit position	Mode	Description
IER	0x02	TC1 IER	2	R/W	0: TC1 interrupt is disabled. (default)
ILK	0X02	ICI_IEK	2		1: TC1 interrupt is enabled.
T1L	0x03	T1L[7:0]	7~0	W	Low byte of TC1 pre-load value
T1H	0x04	T1H[7:0]	7~0	W	High byte of TC1 pre-load value
OP1	0x09	TC1E	2	R / \\ /	0: TC1 is disabled. (default)
OFI	UXU9	TC1E	2		1: TC1 is enabled.





14. Timer2

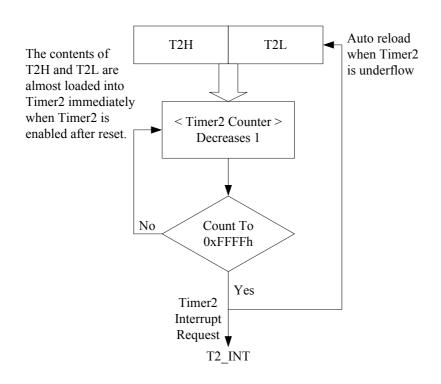
Timer2 is similar in structure to Timer1 except that clock source of Timer2 comes from the system clock "Fsys"/1.5. The system clock "Fsys" varies depending on the operation modes of the MCU.

The Timer2 consists of two 8-bit write-only preload registers T2H and T2L and 16-bit down counter. If Timer2 is enabled, counter will decrement by one with each incoming clock pulse. Timer2 interrupt will be generated when the counter underflows - counts down to FFFFH. And it will be automatically reloaded with the value of T2H and T2L.

Please note that the interrupt signal is generated when counter counts from 0000H to FFFFH. If the value of counter is N, and count down to FFFFH, the total count is N+1. The content of counter is zero when system resets. Once it is enabled to count at this time, the interrupt will be generated immediately and value of T2H and T2L will be loaded since the counter counts to FFFFH. So the T2H and T2L value should be set before enabling Timer2.

The Timer2 related control registers are list as below:

Register	Address	Field	Bit Position	Mode	Description
IER	0x02	TC2 IER	1	R/W	0: TC2 interrupt is disabled. (default)
IEK	0.02	TC2_IER	1	IX/ VV	1: TC2 interrupt is enabled.
T2L	0x05	T2L[7:0]	<i>7</i> ∼0	W	Low byte of TC2 pre-load value
T2H	0x06	T2H[7:0]	7~0	W	High byte of TC2 pre-load value
OP1	000	TCOE	2	R/W	0: TC2 is disabled. (default)
OP1	OP1 0x09 TC2E 3	K/W	1: TC2 is enabled.		







15. Time Base

The TB timer is used to generate time-out interrupt at fixed period. The time-out frequency of TB is determined by dividing slow clock with a factor selected in OP2[3..0]. TBE (Time Base Enable) bit controls enable or disable of the circuit.

OP2	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
Field	IDLE	PNWK	TCWK	TBE		TBS	[30]	
Mode	R/W	R	R	R/W	R/W	R/W	R/W	R/W
Reset	0	-	-	0	-	-	-	-

TBE	Function
0	Disable Time Base
1	Enable Time Base

For example, if the slow clock is 32768 Hz, then the interrupt frequency is as shown in following table.

TBS[30]	Interrupt Frequency
0000	16.384 KHz
0001	8.192 KHz
0010	4.096 KHz
0011	2.048 KHz
0100	1.024 KHz
0101	512 Hz
0110	256 Hz
0111	128 Hz
1000	64 Hz
1001	32 Hz
1010	16 Hz
1011	8 Hz
1100	4 Hz
1101	2 Hz
1110	1 Hz
1111	0.5 Hz

16. Watch Dog Timer

Watch Dog Timer (WDT) is designed to reset system automatically and prevents system dead lock caused by abnormal hardware activities or program execution. The WDT needs to be enabled in Mask Option.

MO_WDTE	Function
0	WDT disable
1	WDT enable

Using the WDT function, the "CLRWDT" instruction needs to be executed in every possible program path when the program runs normally in order to clears the WDT counter before it overflows, so that the





program can operate normally. When abnormal conditions happen to cause the MCU to divert from normal path, the WDT counter will not be cleared and reset signal will be generated to reset the system.

The WDT clock source is the same as TC1 (Timer1 clock), and the WDT reset signal is generated when the counter had counted 32768 clock. The WDT can function in Normal, Slow and Idle Mode. However, WDT will not function during Sleep Mode (as the TC1 clock has stopped).





17. Voice Output

There are 7 or 8 bits DAC/PWM voice output available for user. The 7 bits DAC/PWM output format and configuration are the same as the previous IC of HE80004H series. The 8 bits DAC/PWM format and configuration are new designed and controlled by the VOC and PWMC registers. The selection of 7/8 bits DAC/PWM output is by mask option **MO_8BVOC.**

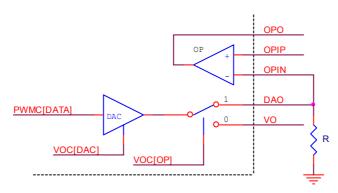
MO_8BVOC	Function
0	7-bit DAC/PWM output
1	8-bit DAC/PWM output

8-Bit DAC/PWM Output:

The Digital-to-Analog converter converts the 8-bit unsigned speech data which is written into PWMC data register to proportional current output.

PWMC	address	Reset	bit 7	bit 6	bit 5	bit 4	bit 3	bit 2	bit 1	bit 0
Field	0x0E		DA7	DA6	DA5	DA4	DA3	DA2	DA1	DA0

There are two output paths for the DAC. Either VO or DAO can be selected as output port of DAC by VOC register when it is enabled. The VO output is primarily intended for speech generation, although it is not necessary so, while the DAO output path can be used in conjunction with built-in OP comparator to function as an Analog-to-Digital Converter as required in applications such as speech recording, speech recognition or sensor interfaces.



The DAC is enabled by DAC bit of VOC register. When DAC is enabled, the DAC output path can be selected to output to DAO or VO pin by OP bit of VOC register.

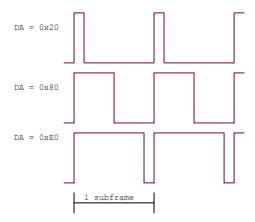
VOC	address	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
Field	0x13	1	PW	/M O/P dri	ver	PWME	PWM	DAC	OP
Reset			0	0	0	0	0	0	0





Bit	Name	Value	Function description
VOC[3]	OC[3] PWME		PWM Output Driver Enable
VOC[3] PWIME		0	PWM Output Driver Disable
VOC[2]	VOC[2] PWM		PWM Module Enable
VOC[2]	P W WI	0	PWM Module Disable
VOC[1]	DAC	1	Digital-to-Analog Converter Enable
VOC[1]	DAC	0	Digital-to-Analog Converter Disable
VOC[0]	VOC[0] OP		DAC output to DAO pin
VOC[0]	Or	0	DAC output to VO pin

The pulse-width modulator (PWM) converts 8-bit unsigned speech data which is written into PWMC data register to proportional duty cycle of PWM output. PWM module shares the same digital input register PWMC with Digit-to-Analog Converter. So PWM and DA output can exist at the same time. When PWM circuit is enabled, it generates signal with duty ratio in proportion to the value of PWMC register.



The PWM bit of VOC controls the enable/disable of the PWM circuit and output driver. When PWM bit of VOC is '0', PWME bit and output drivers are both cleared. To use PWM as voice output, PWM bit has to be set to '1' first, then set PWME bit and enable output driver by setting the driver number. If PWM bit is disabled and enabled again, the setting for driver and PWME bit will be clear.

The Fast Clock is gated through PWME bit of VOC register to provide the clock source of PWM circuit when it is enabled. As PWM needs higher frequency to operate, it cannot generate correct PWM signal in Slow clock only mode.

When the program enters into sleep mode or idle mode, it will automatically turn off all voice outputs by clearing VOC[6:0] to "0000000". To activate voice output again when returning to normal mode, the VOC register needs to be set again.

The PWM output volume can be adjusted by command register VOC[6..4]. The bit 6 and 5 control 2 time driver, while bit 4 controls 1 time driver, thus it has 5 levels of driver output. By turning on/off the internal drivers, the sound level of PWM output can be turned up and down. Please note that this





adjustment apply only to PWM, but not DA output.

PWM output driver selection

VOC[64]	Number of Driver
000	off
001	1
010	2
011	3
100	2
101	3
110	4
111	5

7-Bit DAC/PWM Output:

The 7-bit DAC/PWM voice generator is another scenario and the definitions of PWMC and VOC registers are different from the 8-bit DAC/PWM format. These registers are different from the 8-bit architecture and described as following.

The 7-bit voice output is controlled by PWMC and VOC register, and the PWMC is a command/data register which is determined by PWMC[7] bit. The **VOC** is a three bit voice control register in the 7-bit mode.

VOC	address	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
Field	0x13	-	-	-	-	-	PWM	DAC	OP
Reset	-	-	-	-	-	-	0	0	0

PWM: '1' PWM output enabled; '0' PWM output disabled.

DAC: '1' DAC enabled; '0' DAC disabled.

OP: '1' DAC uses DAO pin as output pin; '0' DAC uses VO pin as output pin.

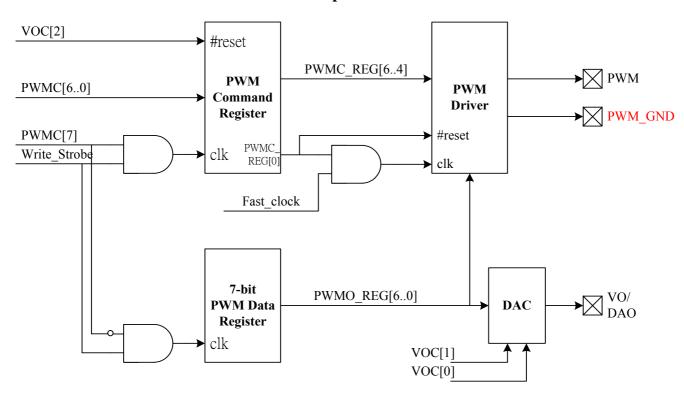
PWMC register	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0		
DA & PWM Data	0		DA and PWM output value							
Control	1	PW	PWM O/P driver Reserved PV							

When users write data into the PWMC register, the PWMC[7] bit will determines the data written into PWM command register or 7-bit data register and the data register is also sent to the DA converter shown as the below diagram. The definitions of "PWME" bit and "PWM O/P driver" bits are the same as VOC register definition of 8-bit output mode.

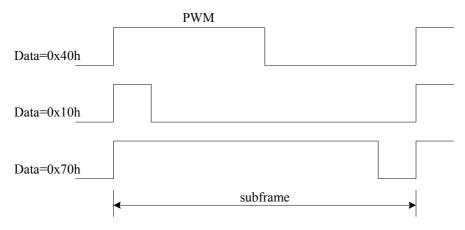




7-bit Voice Output Architecture



The fast clock is used to provide as PWM driver time base, and user shall set the PWMC[7]='1' and VOC[2]='1' to enable the PWM output. When the system enters into sleep or idle mode, it will automatically turn off the voice device by clearing VOC[2:0] to "000". In order to activate voice output again when the system returns and enter into normal mode, the related bits of VOC register need to be set again.

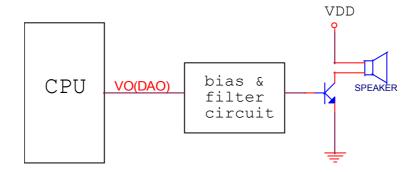


When the DAC is used as sound generator, the bias & filter circuit is used for bias voltage setting and waveform filter regulation and the DAC is output to the VO (Voice Output) pin and please see application notes for detailed calculation example and application. The driving capability of DAC is shown below.

	Condition	Min.	Тур.	Max.	Unit
VO/DAO	V _{DD} =3V;VO=0~2V;Data=7Fh	2.5	3		mA











18. Low Voltage Detection/Reset

The low voltage detection is used to detect low battery or low power condition. There are 4 options on the detection level selectable by mask option MO_DLVL. The low voltage detection circuit can be turned off by clearing LVDE bit, and the status of supply power can be read out at bit LVDO of LVDC register (extension register 0x17h).

MO_DLVL	Detection voltage
00	2.4 volts
01	2.6 volts
10	2.8 volts
11	3.0 volts

LVDC	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
Field	LVDO	-	-	-	-	-	-	LVDE
Mode	R	-	-	-	-	-	-	W
Reset	-	-	-	-	-	-	-	0

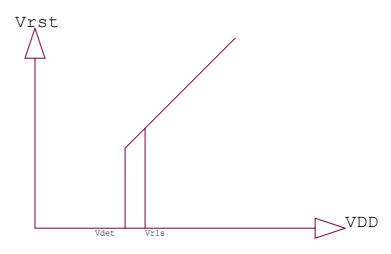
LVDO: '0' → Battery level low; '1' → Battery level high

LVDE: '0' → Disable voltage Detection, '1' → Enable voltage Detection

Low voltage reset circuit prevents the CPU from operating below its physical limit. When the supply voltage drops below V_{DET} (2.2Volt), the CPU will be held in reset state until the supply voltage rises to V_{RLS} . Then CPU will be released from reset state. V_{RLS} will be higher than V_{DET} by 5% to provide hysteresis and prevent CPU from bouncing back and forth between reset and operating state. The low voltage reset function can be enabled or disabled by mask option MO LVRE.

MO_LVRE	Function
0	Disable LVR
1	Enable LVR

The voltage detection circuit is temperature compensated to prevent the detection voltage from drifting with temperature variation.



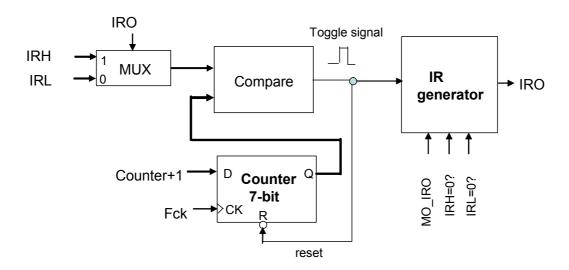




19. Infrared output

To achieve an IR output with programmable frequency and duty cycle, two 7-bit registers are employed here. The IRH register represents the period (on FCK clock number) of output high, while IRL register represents the period of output low. With this mechanism, the output IR frequency is equal to FCK/(IRH+IRL), and the high duty cycle ratio is equal to IRH/(IRH+IRL). To make the IRO as output pin alone, either IRH or IRL can be set as 0. When IRH is 0, the IRO output is a DC low. On the contrary, if IRL is 0, the output is a DC high. Special care in hardware implementation is also taken according to the MO_IRO (mask option to determine the default state of the IRO) to avoid glitch when PWM output is disabled.

IRO



To avoid unexpected IR output, users should firstly load the content of IRH and IRL before turn on IR by set IROE bits to '1'.

The access of all the registers of IR is through the extension register. They are list as below:

Extension register

Address	Name	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	Mode	Reset value
0x15h	IRL	IROE		IR PWM LOW DURATION				R/W	0xxx xxxx		
0x16h	IRH	-		IR	PWM E	HIGH D	URATI	ON		W	-XXX XXXX

IROE: '0' \rightarrow IR is disabled (default); '1' \rightarrow IR is enabled.





20. Universal Asynchronous Receiver/Transmitter

The UART (Universal Asynchronous Receiver/Transmitter) interface provides serial communication capabilities with other devices such as PC. Features include:

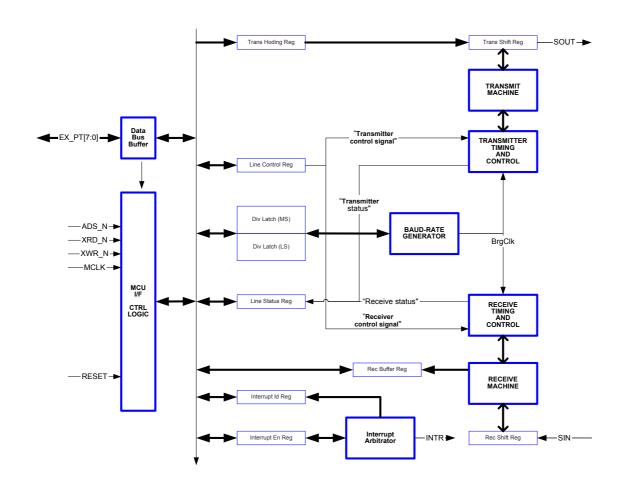
- ✓ Full duplex Asynchronous communication
- ✓ Programmable transmission rate with internal band rate generator with selectable bit rates
- ✓ Double buffered Transmitter and Receiver.
- ✓ Programmable Data length (from 5 to 8 bits)
- ✓ Programmable stop bits (1, 1.5 or 2-stop bit) generation and detection
- ✓ Programmable parity type (odd, even or no parity)
- ✓ Error (parity, overrun and framing errors) detection
- ✓ Fully prioritized interrupt system control
- ✓ Line break generation and detection.

Example – 8-bit UART Frame Format: (1 Start Bit, 8 Data Bits, 1 Parity Bit, 1 Stop Bit)









20.1. Interface Registers

Addressable extension register used to interface with MCU

Address	Name				Func	ction				Mode	RESET		
H00	RBR		UART RECEIVER BUFFER										
01H	THR		UART TRANSMITTER HOLDING REGISTER										
02H	IEIR	0	RLSI	THRI	RBRI	0	ID2	ID1	ID0	R/W	0000 0000		
03H	LCR	BRGE	SB	SP	EPS	PEN	STB	WLS1	WLS0	R/W	0000 0000		
04H	BRL			UART	LSB of Ba	aud Rate R	egister			R/W	0000 0000		
05H	BRH		UART MSB of Baud Rate Register										
06H	LSR	0	TEMT	THRE	BI	FE	PE	OE	DR	R	0110 0000		

IEIR: Interrupt enable/disable identification register.

LCR: Line control register.

LSR: Line status register.

20.2. Baud Rate Configuration Register

The BRH and BRL registers hold the upper and lower bytes of 16 bit baud rate divisor and which are readable/writable. The baud rate of UART is calculated as following:





$$BAUD_RATE_DIVISOR = \frac{FCK}{16*BAUD_RATE}$$
, (FCK: fast clock of system)

The contents of BRH and BRL are calculated by the following two formulas:

The "%" symbol is the modulus operation (reminder of division). For example, if the FCK is 1.8432M Hz and the desired baud rate is 2400 baud, then

$$BAUD_RATE_DIVISOR = \frac{1843200}{16*2400} = 48$$

The BRL register shall be set to 0x30 and BRH set to 0x00. The setting of baud_rate_divisor is not updated until the BRH register is written. Thus user is strongly recommended to write BRL first, then BRH.

In order to obtain good communication quality, the same time base shall be used in the both sides of transmitting and receiving. The following table shows the most common baud rate setting used in the PC UART communication.

BRL and BRH: Baud Rate Control Registers

FCK(Hz)	Baud Rate (bps)	Divisor	BRL	BRH					
1.8432M	50	2304	0x00	0x09					
1.8432M	300	384	0x80	0x01					
1.8432M	1200	96	0x60	0x00					
1.8432M	2400	48	0x30	0x00					
1.8432M	4800	24	0x18	0x00					
1.8432M	9600	12	0x0C	0x00					
1.8432M	19200	6	0x06	0x00					
1.8432M	38400	3	0x03	0x00					
1.8432M	57600	2	0x02	0x00					
1.8432M	115200	1	0x01	0x00					

20.3. Interrupt Enable, Identification Register

This high nibble of IEIR register allows to enable/disable interrupt generation by the UART, the low nibble ID[2..0] of IEIR register is used to identify the source of interrupts.

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Reset Value
0x02h	IEIR	0	RLSI	THRI	RBRI	0	ID2	ID1	ID0	"0000_0000"
		-	R/W	R/W	R/W	-	R	R	R	

RBRI: Receiver Buffer Register Interrupt (1 = Enable, 0 = Disable), related to ID[1] bit.

THRI: Transmitter Hold Register Interrupt (1 = Enable, 0 = Disable), related to ID[0] bit.

RLSI: Receiver Line Status Interrupt (1 = Enable, 0 = Disable), related to ID[2] bit.





The following table shows the related interrupt sources, user can read the ID[2:0] to retrieve what is the current highest priority of pending interrupts. The ID[2:0] bits will be cleared when user read the related registers. For example, when an interrupt happened and the content of ID[2:0] is "101", this means that LRS error and THR empty happen; user can read the LSR register to clear the ID[2] bit and ID[0] bit can also be cleared by reading the IEIR or writing data into THR register.

Level	IEIR Bit [2:0]	Source of Interrupt	Interrupt Reset Control
None	0 0 0	None	None
Highest	100	LSR error flags (OE/PE/FE/BI)	Reading LSR register to clear ID[2]
Second	010	LSR receiver data ready flag (DR)	Reading RBR register to clear ID[1]
Third	0 0 1	LSR flag THR Empty (THRE)	Reading IEIR register or Writing THR register to clear ID[0]

20.4.Line Control Register

The line control register allows user to configure the asynchronous data transfer format and set the UART function. Reading from the register is allowed to check the current settings of the communication.

Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
BRGE	SB	SP	EPS	PEN	STB	WLS1	WLS0

Name	Description
WLS[10]	Word Length Select "00": word length = 5 "01": word length = 6 "10": word length = 7 "11": word length = 8
STB	Stop Bit Length '0': Stop bit length = 1 '1': Stop bit length = 1.5 when WLS[10]="00", else Stop bit length = 2
[SP, EPS, PEN]	Parity Selection "xx0": No Parity "001": odd Parity "011": even Parity "101": Stick Parity 1 "111": Stick parity 0
SB	Set Break When enable the break control bit causes a break condition to be transmitted (SOUT is forced to a logic 0 state). This condition exists until disabled by resetting this bit to logic 0. '0': disable break; '1': enable break
BRGE	Baud Rate Generator '0': disable baud rate clock generator '1': enable baud rate clock generator





20.5.Line Status Register

Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
0	TEMT	THRE	BI	FE	PE	OE	DR

Name	Description
DR	Receiver Data Ready DR indicates status of RBR. It will be set to logic 1 when RBR data is valid and will be reset to logic 0 when RBR is empty. When line errors (OE/PE/FE/BI) happen, DR will also be set to logic 1 and RBR will be updated to reflect the Data bits portion of the frame.
OE	Overrun Error This bit will be set when the next character is transferred into RBR before the previous RBR data is read by the CPU. Even though DR will still be 1 when OE is set to logic 1, the previous frame data stored in RBR which is not read by the CPU is trashed and can't be recovered.
PE	Parity Error This bit will be set to logic 1 only when the Parity is enabled and the Parity bit is not at the logic state it should be. For Even Parity, the Parity bit should be 1 if an odd number of 1s in the Data bits is received; otherwise, the Parity bit should be 0. For Odd Parity, the Parity bit should be 1 if an even number of 1s in the Data bits is received; otherwise, the Parity bit should be 0. For Stick Parity '1', the Parity bit should be 1. For Stick Parity '0', the Parity bit should be 0.
FE	Framing Error FE will be reset to logic 0 whenever SIN is sampled high at the center of the first Stop bit, regardless of how many Stop bits the UART is configured to.
ВІ	Break Interrupt BI will be set to logic 1 whenever SIN is low for longer than the whole frame (the time of Start bit + Data bits + Parity bit + Stop bits), not at the SIN rising edge where Break is negated. If SIN is still low after BI is reset to logic 0 by reading LSR, BI will not be set to logic 1 again. Since Break is also a Framing error, FE will also be set to 1 when BI is set.
THRE	THR Empty THRE will be set to logic 1 whenever THR is empty which indicates that the transmitter is ready to accept new data to transmit.
ТЕМТ	Both THR and TSR are Empty This bit will be set to logic 1 when THRE is set to 1 and the last Data bit in the TSR is shifted out through SOUT.

^{*} The four error flags (OE, PE, FE and BI) of LSR will be reset to logic 0 after a LSR read.

Since the SIN and SOUT of UART pins are shared with PRTD[1..0], users can use the mask option to enable the UART function and select PRTD[1..0] function.

MO HART	0	PRTD[1:0] = I/O Pin
MO_UART	1	PRTD[1:0] = UART Pin





21. Extension Register Access

The extension registers can be accessed through the extension port control registers EXTAS and EXTDA. User can read/write the extension register easily and the control timing is generated by hardware automatically. The following code shows how to access the extension registers.

Read Extension Register:

LDA #0x00h; load #0x00h data to A Register

STA EXTAS ; store A register data to the extension port address register.

LDA EXTDA ; store the extension register (0x00h) data to A Register.

Write Extension Register:

LDA #0x03h; load #0x03h data to A Register

STA EXTAS ; store A register data to the extension port address register.

LDA #0x18h; load #0x18h data to A Register

STA EXTDA; store A register data to the extension port data register.

22. Summary of Registers and Mask Options

All the registers and mask options used in this chip are listed in the following tables.

Adduses	NAME					.1.1				Mada	DECET		
Address				т		eld D. A				Mode			
00H	TPL					er Low Byte				R/W	XXXX XXXX		
01H	TPH		1			er High Byt				R/W	XXXX XXXX		
02H	IER	-	-	INT_EX	TB	INT1	T1	T2	INT2	R/W	00 0000		
03H	T1L					Low Byte				W	XXXX XXXX		
04H	T1H		Timer 1 High Byte										
05H	T2L		Timer 2 Low Byte										
06H	T2H				Timer 2 I	High Byte				W	xxxx xxxx		
07H	SP				Stack 1	Pointer				R/W	1111 1111		
08H	DP				RAM]	Pointer				R/W	XXXX XXXX		
09H	OP1	DRDY	STOP	SLOW	INTE	T2E	T1E	Z	С	R/W	1000 00xx		
0AH	OP2	IDLE	PNWK	TCWK	TBE		TBS[30]		R/W	0xx0		
0BH	PP				RAM Pag	ge Pointer		_		R/W	0000 0000		
0CH	PRTC	PRTC[7]	PRTC[6]	PRTC[5]	PRTC[4]		Rese	rved		R/W	1111		
0DH	PRTD				I/O P	ort D				R/W	1111 1111		
0EH	PWMC				PWM	I Data				W	0000 0000		
0FH	LCDC	-	-	CLR_GP		Reserved		BLANK	LCDE	W	xx1x xx10		
13H	VOC	-	PW	/M O/P dri	ver	PWME	PWM	DAC	OP	R/W	x000 0000		
14H	PRT14				I/O P	ort 14				R/W	1111 1111		
15H	PRT15				I/O P	ort 15				R/W	1111 1111		
16H	TPP			R	OM Table	Page Pointe	er			R/W	0000 0000		
17H	PRT17		I/O Port 17										
20H	EXTAS		Extension Port Address Register										
21H	EXTDA		Extension Port Data Register										
22H	KEYR0	R	RI[1]	RI[0]	CI[4]	CI[3]	CI[2]	CI[1]	CI[0]	R/W	xxxx xxxx		
23H	KEYR1	0	RI[1]	RI[0]	CI[4]	CI[3]	CI[2]	CI[1]	CI[0]	R/W	XXXX XXXX		





Address	NAME				Fic	eld				Mode	RESET	
24H	LCDPS	-	ı	-	1	-	POWDN	PAcc	BUFE	R/W	100	
2BH	GRAY16			32 to 16	6 Gray Lev	el Palette R	Register			W		
	GRAY0			Gray	Level 0 M	apping Reg	gister			W	xxx0 0000	
	GRAY1			Gray	Level 1 M	apping Reg	gister			W	xxx0 0010	
	GRAY2		Gray Level 2 Mapping Register									
	GRAY3		Gray Level 3 Mapping Register									
	GRAY4		Gray Level 4 Mapping Register									
	GRAY5		Gray Level 5 Mapping Register									
	GRAY6			Gray	Level 6 M	apping Reg	gister			W	xxx0 1100	
	GRAY7					apping Reg				W	xxx0 1110	
	GRAY8					apping Reg				W	xxx1 0000	
	GRAY9					apping Reg				W	xxx1 0010	
	GRAYA					Iapping Reg				W	xxx1 0100	
	GRAYB					lapping Reg				W	xxx1 0110	
	GRAYC					Sapping Reg				W	xxx1 1000	
	GRAYD					Iapping Reg				W	xxx1 1010	
	GRAYE					apping Reg				W	xxx1 1100	
	GRAYF					apping Reg				W	xxx1 1110	
2CH	PSA1						for Logical			R/W	0000 0001	
2DH	PSA2						for Logical			R/W	0000 0010	
2EH	PSA3		Physical				for Logical	Page 3		R/W	0000 0011	
30H	AC					address cou				R/W		
	ACL	AC7	AC6	AC5	AC4	AC3	AC2	AC1	AC0	R/W	0000 0000	
	ACH	AC15	AC14	AC13	AC12	AC11	AC10	AC9	AC8	R/W	0000 0000	
	ACP	AC23	AC22	AC21	AC20	AC19	AC18	AC17	AC16	R/W	0000 0000	
31H	EXMD			D	ownload B	us Data Po				R/W	XXXX XXXX	
32H	EXMC	-	-	-	-	-	WR	RD	DNLD	R/W	xxxx x011	

Extension registers:

Address	Name				Fund	ction				Mode	RESET
H00	RBR			J	JART Rec	eiver Buffe	er			R	0000 0000
01H	THR				R/W	0000 0000					
02H	IEIR	0	RLSI	THRI	RBRI	0	ID2	ID1	ID0	R/W	0000 0000
03H	LCR	BRGE	SB	SP	EPS	PEN	STB	WLS1	WLS0	R/W	0000 0000
04H	BRL			UART	LSB of B	aud Rate R	egister			R/W	0000 0000
05H	BRH			UART	MSB of B	aud Rate F	Register			R/W	0000 0000
06H	LSR	0	TEMT	THRE	BI	FE	PE	OE	DR	R	0110 0000
15H	IRL	IROE		IR PWM Low Duration							
16H	IRH	-				W	-xxx xxxx				
17H	LDVC	LVDO	-	-	-	-	-	-	LVDE	R/W	x0

Mask Options:

NAME	Value	Description			
MO LVRE	0	Low Voltage Reset Disable			
MC_HVRE	1	Low Voltage Reset Enable			
MO FXTAL	0	R/C Oscillator Used for Fast Clock			
MO_FATAL	1	X'tal Oscillator Used for Fast Clock			
MO SXTAL	0	R/C Oscillator Used for Slow Clock			
MO_SXIAL	1	X'tal Oscillator Used for Slow Clock			
MO_FCK/SCKN 00 Slow Clock Only		Slow Clock Only			
	01	illegal			





NAME	Value	Description				
	10	Dual Clock				
	11	Fast Clock Only				
MO WDTE	0	WDT Disable				
MO_WDIE	1	WDT Enable				
MO CDD [7 · 4]	0	Open-drain Output				
MO_CPP[7:4]	1	Push-pull Output				
MO DDD [7:0]	0	Open-drain Output				
MO_DPP[7:0]	1	Push-pull Output				
MO 14DD[7.0]	0	Open-drain Output				
MO_14PP[7:0]	1	Push-pull Output				
MO 15PP[7:0]	0	Open-drain Output				
MO_13PP[/:0]	1	Push-pull Output				
MO 17PP[7:0]	0	Open-drain Output				
MO_17FF[7:0]	1	Push-pull Output				
MO LIO14[7:0]	0	PRT14 used as IO pin				
MO_HIGI4[7:0]	1	PRT14 used as LCD pin				
MO LIO15[7:0]	0	PRT15 used as IO pin				
MO_HIG15[7:0]	1	PRT15 used as LCD pin				
MO LIO17[7:0]	0	PRT17 used as IO pin				
10_11017[7:0]	1	PRT17 used as LCD pin				
	00	LCD Configuration = 32COM x 128SEG				
MO COM[1:0]	01	LCD Configuration = 48COM x 112SEG				
110_001[1:0]	10	LCD Configuration = 64COM x 96SEG				
	11	LCD Configuration = 80COM x 80SEG				
	00	LCD Bias= 1/7				
MO LBSR[1:0]	01	LCD Bias= 1/8				
	10	LCD Bias= 1/9				
	11	LCD Bias= 1/10				
	00	Temperature Coefficient of Regulator Voltage = -0.00 %/℃				
MO_TC[1:0]	01	Temperature Coefficient of Regulator Voltage = -0.16 %/℃				
1.0_10[1.0]	10	Temperature Coefficient of Regulator Voltage = -0.22 %/℃				
	11	Temperature Coefficient of Regulator Voltage = -0.33 %/℃				
	00	LCD driving current= "Low"				
MO LOAD[1:0]	01	LCD driving current= "Medium"				
10_101D [1:0]	10	LCD driving current= "Medium High"				
	11	LCD driving current= "High"				
MO LCDKEY	0	LCD SGKY[43:24] Used as SEG only				
110_11051td1	1	LCD SGKY[43:24] Used as SEG/KEY_SCAN				
	00	Scan Pulse Width = 0.5 SCK				
MO_SNCK[1:0]	01	Scan Pulse Width = 1.0 SCK				
	10	Scan Pulse Width = 1.5 SCK				
	11	Scan Pulse Width = 2.0 SCK				
	00	Strength of Key Scan = Weakest				
MO_SCDRV[1:0]	01	Strength of Key Scan = Weak				
	10	Strength of Key Scan = Strong				
	11	Strength of Key Scan = Strongest				
MO_RCAP[2:0]	000	Capacitor Selection: C=2P => 4M Hz(R=30k)				





NAME	Value	Description				
	001	Capacitor Selection: C=4P => 4M Hz(R=17k)				
	010	Capacitor Selection: C=7P => 4M Hz(R=11k)				
	011	Capacitor Selection: C=14P => 1M Hz(R=25k)				
	100	Capacitor Selection: C=20P => 1M Hz(R=18k)				
	101	Capacitor Selection: C=40P => 500K Hz(R=19k)				
	110	Capacitor Selection: C=50P => 500K Hz(R=15k)				
	111	Capacitor Selection: C=60P => 500K Hz(R=13k)				
MO 8BVOC	0	7 bit DAC/PWM Voice Output				
MO_8BVOC	1	8 bit DAC/PWM Voice Output				
	0.0	16 GRAY LEVEL				
MO GRAY MODE[1:0]	01	4 GRAY LEVEL				
MO_GRAI_MODE[1:0]	10	2 LEVEL(B/W)				
	11	2 LEVEL(B/W)				
мо ехмем	0	Internal MEMORY Used Only				
MO_EXMEM	1	External MEMORY Used.				
	00	Low Voltage Detection Level= 2.4V				
MO DLVL[1:0]	01	Low Voltage Detection Level= 2.6V				
MO_DHVH[1:0]	10	Low Voltage Detection Level= 2.8V				
	11	Low Voltage Detection Level= 3.0V				
MO IRO	0	Default State of the IRO After Reset: Low				
MO_IRO	1	Default State of the IRO After Reset: High				
	0.0	ROM MAP Configuration Option 0				
MO PMODE[1:0]	01	ROM MAP Configuration Option 1				
MO_PMODE[1:0]	10	ROM MAP Configuration Option 2				
	11	ROM MAP Configuration Option 3				
MO UART	0	PRTD[1:0] = I/O Pin				
-10_01111	1	PRTD[1:0] = UART Pin				
MO PUMPE	0	Disable Internal Charge-pump				
LIO_I OMEE	1	Enable Internal Charge-pump				





23. Absolute Maximum Rating

Item	Symbol	Rating	Condition
Supply Voltage	V_{DD}	$-0.5V \sim 4.0V$	
Input Voltage	V_{IN}	$-0.5V \sim V_{DD} + 0.5V$	
Output Voltage	V_{O}	$-0.5V \sim V_{DD} + 0.5V$	
Operating Temperature	T_{OP}	$0^{\circ}\text{C} \sim 70^{\circ}\text{C}$	
Storage Temperature	T_{ST}	$-50^{\circ}\text{C} \sim 100^{\circ}\text{C}$	

24. Recommended Operating Conditions

Item	Symbol	Rating	Condition
Supply Voltage	$V_{ m DD}$	$2.4V \sim 3.6V$	
T XX 1.	V_{IH}	$0.9~V_{DD} \sim V_{DD}$	
Input Voltage	$ m V_{IL}$	$0.0V\sim0.1V_{DD}$	
		8M Hz	$V_{DD} = 3.0 V$
Operating Frequency	F_{MAX} .	6M Hz	$V_{DD} = 2.4V$
Operating Temperature	T_{OP}	$0^{\circ}\text{C} \sim 70^{\circ}\text{C}$	
Storage Temperature	T_{ST}	$-50^{\circ}\text{C} \sim 100^{\circ}\text{C}$	

25. AC/DC Characteristics

Testing Condition: TEMP=25°C, VDD=3V±10%

Parameters	Symbol	Min.	Тур.	Max.	Unit	Condition
Power consumption		_				
NORMAL Mode Current	I_{FAST}		1	1.5	mA	2M external R/C fast clock
SLOW Mode Current	I_{SLOW}		15	25	μΑ	32768 Hz slow clock with LCD disabled
IDLE Mode Current	I_{IDLE}		10	20	μΑ	32768 Hz slow clock with LCD disabled
Sleep Mode Current	I_{SLEEP}			1	μΑ	LVR and LVD disable
Additional Current if LCD			200	220		LV5=3×LVREG
ON	I_{LCD}		250	275	۸	LV5=4×LVREG
ON			300	330	μA	LV5=5×LVREG
I/O specification		_				
Input High Voltage	$V_{ m IH}$	0.8			V_{DD}	Input Pins
Input Low Voltage	V_{IL}			0.2	V_{DD}	Input Pins
	V _{HYS}	5 0	1/3	$V_{ m DD}$		I/O, RSTP_N Threshold = 2/3 VDD
Input Hysteresis Width					V _{DD}	(Input from low to high), Threshold = $1/3$
						VDD (Input from high to low)
Output Source Current	I_{OH}	50			μA	Output drive high*1, V _{OH} =2.0V
Output Sink Current	I_{OL1}	1.0			mA	Output drive low, V _{OL} =0.4V
Input Low Current	I_{IL1}		20		μΑ	$RSTP_N$, $V_{IL} = GND$, $Pull high$
Input Low Current	1 L1		20		μΑ	Internally
Input Low Current	$I_{\rm IL2}$		100		μΑ	I/O, V _{IL} =GND, if pull high Internally by
			100			user
PWM and DAC						
		10	14		mA	PWM ^{*2} With 32Ω Loading
PWM Output Current	I_{PWM}	6	8		mA	With 64Ω Loading
		4	5		mA	With 100Ω Loading





DAC Output Current	I_{VO}	2.5	3		mA	VO, DAO@ V _{DD} =3V,VO=0~2V, Data =FF
Low voltage Reset				_	_	
LVR detection voltage	V_{DET}		2.2		Volts	
LVR release voltage	V_{RLS}		2.31		Volts	
IR Output Sink/Source Current	I_{O}		20		mA	V_{OL} =0.4V, V_{OH} =2.0V
LVR power consumption	I_{LVR}		10		μΑ	When LVR is enabled

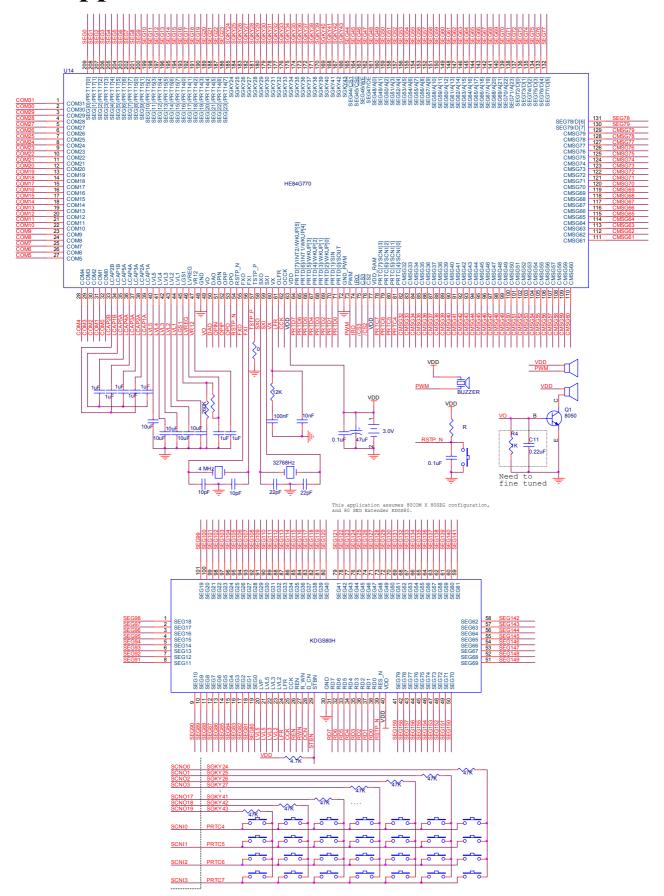
Notes:

- 1. The "Output Source Current" specification is applicable only to the Push-Pull I/O type.
- 2. This Specification indicates only one PWM driving capability, and there are totally five built-in drivers, user can multiply the actual number of driver to get the total amount of current. ($I_{PWM} \times N$; N=0, 1, 2, 3, 4, 5)





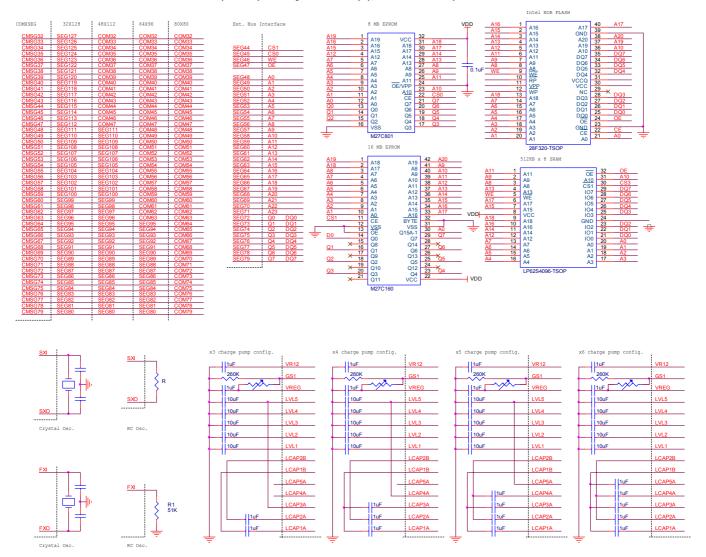
26. Application Circuit







Note: Options for system configuration of LCD Display, Osc. and external memory.







27. Important Note

- 1. Please note that ICE is different from IC which is your target chip. The ICE is a superset of HE80004H series IC, but each IC is a subset of ICE. Don't use any hardware resource that your target chip doesn't have them, especially RAM and register. KBIDS and compiler can't prevent user from using some hardware resources that don't exist in your target chip.
- 2. To access "Data ROM", users must update TPP first, TPH, and then TPL. Only follow this order, the pre-charge circuit of ROM will work correctly. The 5µs waiting is also necessary before LDV instruction is executed since Data ROM is a low speed ROM. User can't emulate this accessing process in ICE, so 5µs delay should be added by firmware.
- 3. Please bond the TSTP_P, RSTP_N and PRTD [7:0] with test points on PCB (can be soldered and probed) as you can, then some testing can be performed on PCB when it's necessary. The TSTP_P is suggested to connect to ground by a 0 ohm resistor. The following figure is an example (Testing point with through hole).
- 4. The LV5 must be lower than 12 Volt; otherwise the chip may be damaged.

28. Updated History

Version	Date	Revised History						
V1.0	7/22/03	New Released						
V1.1	10/31/03	 Modify the 7-bit DAC block diagram Change the product name from HE84G770H to HE84G770 						